

1. Safety Precautions

1-1. Repair Precaution

Before attempting any repair or detailed tuning, shield the device from RF noise or static electricity discharges.

Use only demagnetized tools that are specifically designed for small electronic repairs, as most electronic parts are sensitive to electromagnetic forces.

Use only high quality screwdrivers when servicing products. Low quality screwdrivers can easily damage the heads of screws.

Use only conductor wire of the properly gauge and insulation for low resistance, because of the low margin of error of most testing equipment.

We recommend 22-gauge twisted copper wire.

Hand-soldering is not recommended, because printed circuit boards (PCBs) can be easily damaged, even with relatively low heat. Never use a soldering iron with a power rating of more than 100 watts and use only lead-free solder with a melting point below 250°C (482°F).

Prior to disassembling the battery charger for repair, ensure that the AC power is disconnected.

Always use the replacement parts that are registered in the SEC system. Third-party replacement parts may not function properly.

1. Safety Precautions

1-2. ESD(Electrostatically Sensitive Devices) Precaution

Many semiconductors and ESDs in electronic devices are particularly sensitive to static discharge and can be easily damaged by it. We recommend protecting these components with conductive anti-static bags when you store or transport them.

Always use an anti-static strap or wristband and remove electrostatic buildup or dissipate static electricity from your body before repairing ESDs.

Ensure that soldering irons have AC adapter with ground wires and that the ground wires are properly connected.

Use only desoldering tools with plastic tips to prevent static discharge.

Properly shield the work environment from accidental electrostatic discharge before opening packages containing ESDs.

The potential for static electricity discharge may be increased in low humidity environments, such as air-conditioned rooms. Increase the airflow to the working area to decrease the chance of accidental static electricity discharges.

2. Specification

2-1. GSM General Specification

Item		GSM 850	EGSM 900	DCS1800	PCS1900
Freq. Band[MHz]		824~849	880~915	1710~1785	1850~1910
Uplink/Downlink		869~894	925~960	1805~1880	1930~1990
ARFCN range		128~251	0~124 & 975~1023	512~885	512~810
Tx/Rx spacing		45MHz	45MHz	95MHz	80MHz
Mod. Bit rate/ Bit Period		270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us
Time Slot Period/ Frame Period		576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms
Modulation	GSM/ EGPRS	GMSK/ 8PSK	GMSK/ 8PSK	GMSK/ 8PSK	GMSK/ 8PSK
MS Power		33dBm~5dBm	33dBm~5dBm	30dBm~0dBm	30dBm~0dBm
Power Class		4(GMSK) E2(8PSK)	4(GMSK) E2(8PSK)	1(GMSK) E2(8PSK)	1(GMSK) E2(8PSK)
Sensitivity		-102dBm	-102dBm	-100dBm	-100dBm
TDMA Mux		8	8	8	8

2. Specification

2-2. WCDMA General Specification

Item	WCDMA 2100(B1)	WCDMA 800(B19)	WCDMA 800(B6)	WCDMA 850(B5)
Freq. Band[MHz] Uplink/Downlink	1922.4~1977.6 2112.4~2167.6	830~845 875~890	830~840 875~885	826.4~846.6 871.4~891.6
ARFCN range	UL: 9612~9888 DL: 10562~10838	UL: 312~363 DL: 712~763	UL: 4162~4188 DL: 4387~4413	UL: 4132~4233 DL: 4357~4458
Tx/Rx spacing	190MHz	45MHz	45MHz	45MHz
Mod. Bit rate/ Bit Period	14.4Mbps(DL) 5.76Mbps(UL)	14.4Mbps(DL) 5.76Mbps(UL)	14.4Mbps(DL) 5.76Mbps(UL)	14.4Mbps(DL) 5.76Mbps(UL)
Time Slot Period/ Frame Period	WCDMA 10ms/0.667ms HSPA 2ms/0.667ms	WCDMA 10ms/0.667ms HSPA 2ms/0.667ms	WCDMA 10ms/0.667ms HSPA 2ms/0.667ms	WCDMA 10ms/0.667ms HSPA 2ms/0.667ms
Modulation	QPSK HPSK 16QAM 64QAM	QPSK HPSK 16QAM 64QAM	QPSK HPSK 16QAM 64QAM	QPSK HPSK 16QAM 64QAM
MS Power (dBm)	24dBm ~ -50dBm	24dBm ~ -50dBm	24dBm ~ -50dBm	24dBm ~ -50dBm
Power Class	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)
Sensitivity	-106.7dBm	-106.7dBm	-106.7dBm	-104.7dBm

2. Specification

2-3. LTE General Specification

Item	LTE FDD B1	LTE FDD B3
Tx Freq. range	1920~1980 MHz	1710~1785 MHz
Rx Freq. range	2110~2170 MHz	1805~1880 MHz
Channel Bandwidth	5, 10,15, 20 MHz	1.4, 3, 5, 10,15, 20 MHz
Duplex Separation	90MHz	95MHz
Modulation	Uplink DCM : QPSK/16QAM KDDI : QPSK/16QAM/64QAM Downlink DCM : QPSK/16QAM/64QAM/256QAM KDDI : QPSK/16QAM/64QAM/256QAM	Uplink DCM : QPSK/16QAM KDDI : QPSK/16QAM/64QAM Downlink DCM : QPSK/16QAM/64QAM/256QAM KDDI : QPSK/16QAM/64QAM/256QAM
MS Power	-40dBm~ 25dBm	-40dBm~ 25dBm
Power Class	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)
Sensitivity	-98 (BW : 5 MHz) -95 (BW : 10 MHz) -93.2 (BW : 15MHz) -92 (BW : 20MHz)	-98 (BW : 5 MHz) -95 (BW : 10 MHz) -93.2 (BW : 15MHz) -92 (BW : 20MHz)
Cell Radius	>5Km	>5Km
In/Output Impedance	50Ω	50Ω
Operating Temperature	-30°C ~ +60°C	-30°C ~ +60°C

2. Specification

Item	LTE FDD B19	LTE FDD B21	LTE FDD B26
Tx Freq. range	830~845 MHz	1447.9~1462.9 MHz	814~849 MHz
Rx Freq. range	875~890 MHz	1495.9~1510.9 MHz	859~894 MHz
Channel Bandwidth	5, 10, 15 MHz	5, 10, 15 MHz	5, 10, 15 MHz
Duplex Separation	45 MHz	48 MHz	45 MHz
Type of Emission	Uplink DCM : QPSK/16QAM Downlink DCM : QPSK/16QAM/64QAM/256QAM	Uplink DCM : QPSK/16QAM Downlink DCM : QPSK/16QAM/64QAM/256QAM	Uplink KDDI : QPSK/16QAM/64QAM Downlink KDDI : QPSK/16QAM/64QAM/256QAM
MS Power	-40dBm~ 25dBm	-40dBm~ 25dBm	-40dBm~ 25dBm
Power Class	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)
Sensitivity	-98 (BW : 5 MHz) -95 (BW : 10 MHz) -93.2 (BW : 15MHz) -92 (BW : 20MHz)	-98 (BW : 5 MHz) -95 (BW : 10 MHz) -93.2 (BW : 15MHz) -92 (BW : 20MHz)	-98 (BW : 5 MHz) -95 (BW : 10 MHz) -93.2 (BW : 15MHz) -92 (BW : 20MHz)
Cell Radius	>5Km	>5Km	>5Km
In/Output Impedance	50Ω	50Ω	50Ω
Operating Temperature	-30°C ~ +60°C	-30°C ~ +60°C	-30°C ~ +60°C

2. Specification

Item	LTE FDD B28	LTE FDD B41	LTE FDD B42
Tx Freq. range	703~748 MHz	2496 ~ 2690 MHz	3400~3600 MHz
Rx Freq. range	758~803 MHz	2496 ~ 2690 MHz	3400~3600 MHz
Channel Bandwidth	5, 10, 15, 20 MHz	5, 10, 15, 20 MHz	5, 10, 15, 20 MHz
Duplex Separation	55 MHz	N/A	N/A
Type of Emission	Uplink DCM : QPSK/16QAM Downlink DCM : QPSK/16QAM/64QAM/256QAM	Uplink KDDI : QPSK/16QAM/64QAM Downlink KDDI : QPSK/16QAM/64QAM/256QAM	Uplink DCM : QPSK/16QAM KDDI : QPSK/16QAM/64QAM Downlink DCM : QPSK/16QAM/64QAM/256QAM KDDI : QPSK/16QAM/64QAM/256QAM
MS Power	-40dBm~ 25dBm	-40dBm~ 25dBm	-40dBm~ 25dBm
Power Class	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)	3 (max: 23 ±2dBm)
Sensitivity	-98 (BW : 5 MHz) -95 (BW : 10 MHz) -93.2 (BW : 15MHz) -92 (BW : 20MHz)	-98 (BW : 5 MHz) -95 (BW : 10 MHz) -93.2 (BW : 15MHz) -92 (BW : 20MHz)	-98 (BW : 5 MHz) -95 (BW : 10 MHz) -93.2 (BW : 15MHz) -92 (BW : 20MHz)
Cell Radius	>5Km	>5Km	>5Km
In/Output Impedance	50Ω	50Ω	50Ω
Operating Temperature	-30°C ~ +60°C	-30°C ~ +60°C	-30°C ~ +60°C

2. Specification

2-4. GSM Tx Power Class

TX Power control level	GSM850	TX Power control level	EGSM900	TX Power control level	DCS1800	TX Power control level	PCS1900
5	33±2 dBm	5	33±2 dBm	0	30±3 dBm	0	30±3 dBm
6	31±2 dBm	6	31±2 dBm	1	28±3 dBm	1	28±3 dBm
7	29±2 dBm	7	29±2 dBm	2	26±3 dBm	2	26±3 dBm
8	27±2 dBm	8	27±2 dBm	3	24±3 dBm	3	24±3 dBm
9	25±2 dBm	9	25±2 dBm	4	22±3 dBm	4	22±3 dBm
10	23±2 dBm	10	23±2 dBm	5	20±3 dBm	5	20±3 dBm
11	21±2 dBm	11	21±2 dBm	6	18±3 dBm	6	18±3 dBm
12	19±2 dBm	12	19±2 dBm	7	16±3 dBm	7	16±3 dBm
13	17±2 dBm	13	17±2 dBm	8	14±3 dBm	8	14±3 dBm
14	15±2 dBm	14	15±2 dBm	9	12±4 dBm	9	12±4 dBm
15	13±2 dBm	15	13±2 dBm	10	10±4 dBm	10	10±4 dBm
16	11±3 dBm	16	11±3 dBm	11	8±4 dBm	11	8±4 dBm
17	9±3dBm	17	9±3dBm	12	6±4 dBm	12	6±4 dBm
18	7±3 dBm	18	7±3 dBm	13	4±4 dBm	13	4±4 dBm
19	5±3 dBm	19	5±3 dBm	14	2±5 dBm	14	2±5 dBm
-	-	-	-	15	0±5 dBm	15	0±5 dBm

3. Product Function

Main Function

Item	Description
OS	Android V8.0
RF	[2G] GSM 850(B5)/900(B8)/1800(B3)/1900(B2) [3G] WCDMA : B1 / B5 / B6 / B19 [4G(LTE)] - FDD : B1 / B3 / B4 / B5 / B7 / B12/ B13 /B17 / B19 / B21 / B26 / B28 - TDD : B38 / B39 / B40 / B41 / B42
Battery	3,500mAh
Base Band	SDM845 / 2.8GHz, 1.7GHz
Other RF	GPS, GLONASS, BEIDOU, GALILEO, QZSS, BT 5.0, USB 3.1, WIFI 802.11 a/b/g/n/ac (2.4G+5GHz), NFC, FeliCa, ISDBT
Camera	Dual Camera (Wide : 12M Dual A/F, OIS, F1.5-2.4 & Tele : 12M, OIS, F2.4) with LED Flash, Front : 8MP A/F (Front), 5.8MP (IRIS)
LCD	6.2" Quad HD+, 2960 x 1440, dual edge Super AMOLED
RAM	6GB LPDDR4X + 64GB UFS
Sensor	Accelerometer, Barometer, Fingerprint Sensor, Gyro Sensor, Geomagnetic Sensor, Hall Sensor, HR Sensor, Iris Sensor, Pressure Sensor, Proximity Sensor, RGB Light Sensor
Accessory	Charger : 5V/2A or 9 V/1.67 A Data cable : USB Type-C Earjack : 3.5pi, 4Pin

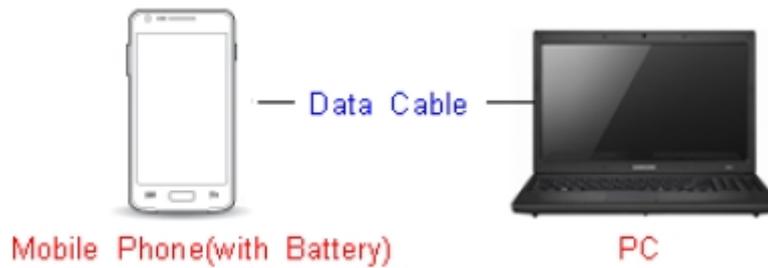
6. Level 1 Repair

6-1. S/W Update

6-1-1. Preparation

- S/W Update program : [Fenrir 5.17.xxxx](#)
- Mobile Phone
- Data Cable

※ Settings



Data Cable : GH39-01949A

6. Level 1 Repair

6-1-2. How to use 'Fenrir' S/W update program.

1) Launch Fenrir by clicking on the icon on the desktop



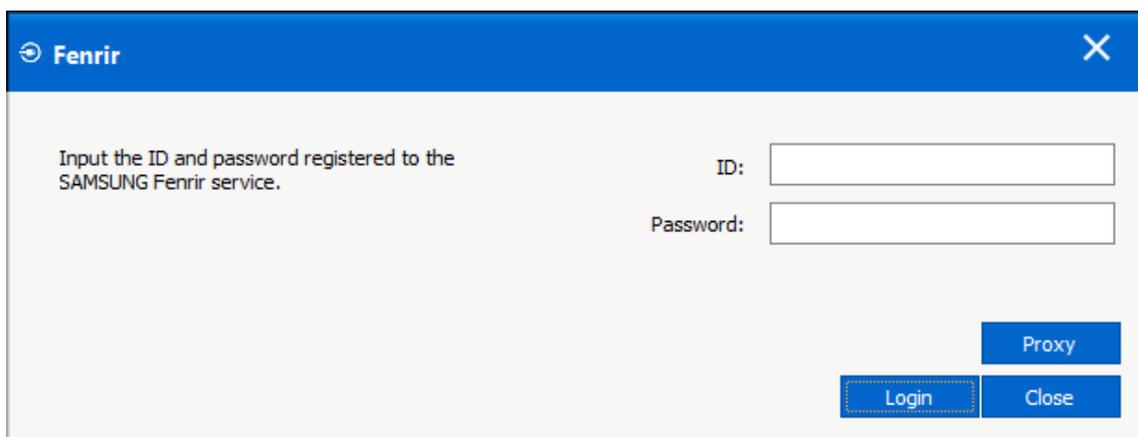
- SVH (Fenrir_Home) : It uses Home binary which does not have user data area in the memory when flashed to a device. (Keep user data)

- SVC (Fenrir_Factory) : It uses Factory binary which erases all user data in the memory when flashed to a device. (Clear user data)

- SVA (Fenrir_All) : It uses Factory and Home binaries. you can download Home and Factory binary in a PC (but requires double HDD storage and NW traffic)

2) Input ID & password

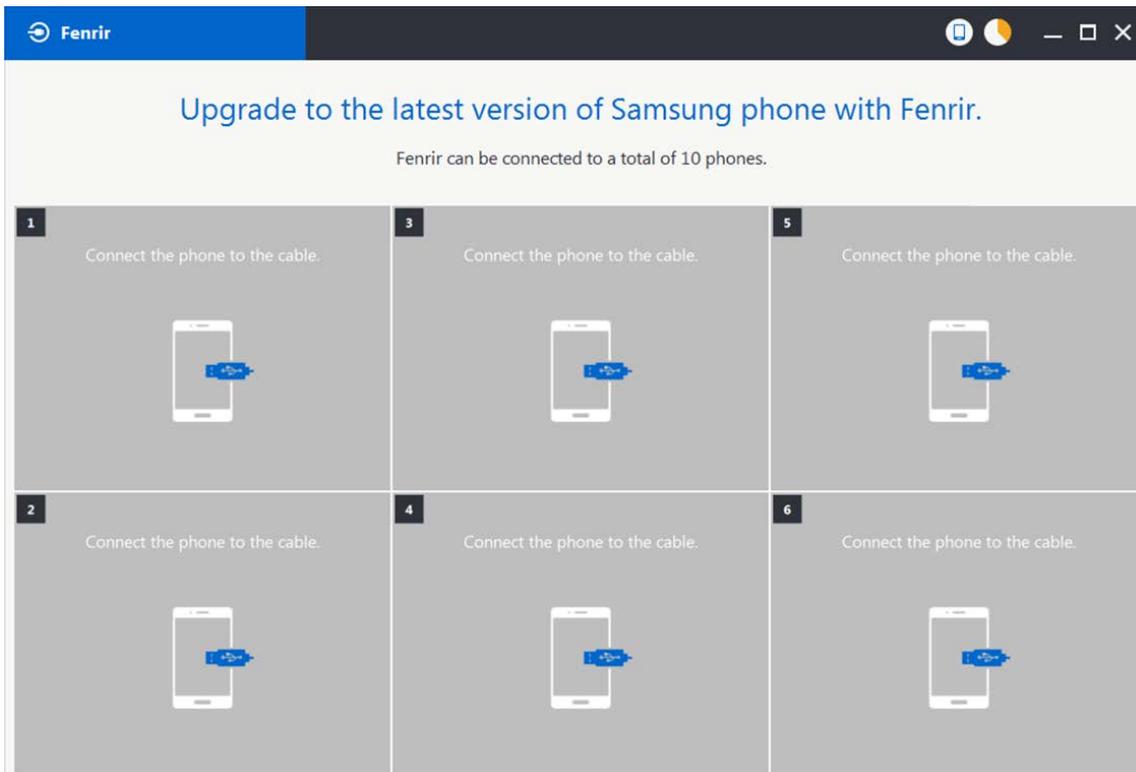
※ You need to reset the ID information in case of PC change and format and repair, hard disk change



The screenshot shows the Fenrir software interface. At the top, there is a blue header with the Fenrir logo and a close button (X). Below the header, the text reads: "Input the ID and password registered to the SAMSUNG Fenrir service." To the right of this text are two input fields: "ID:" and "Password:". Below the input fields are three buttons: "Proxy", "Login", and "Close". The "Login" button is highlighted with a dashed border.

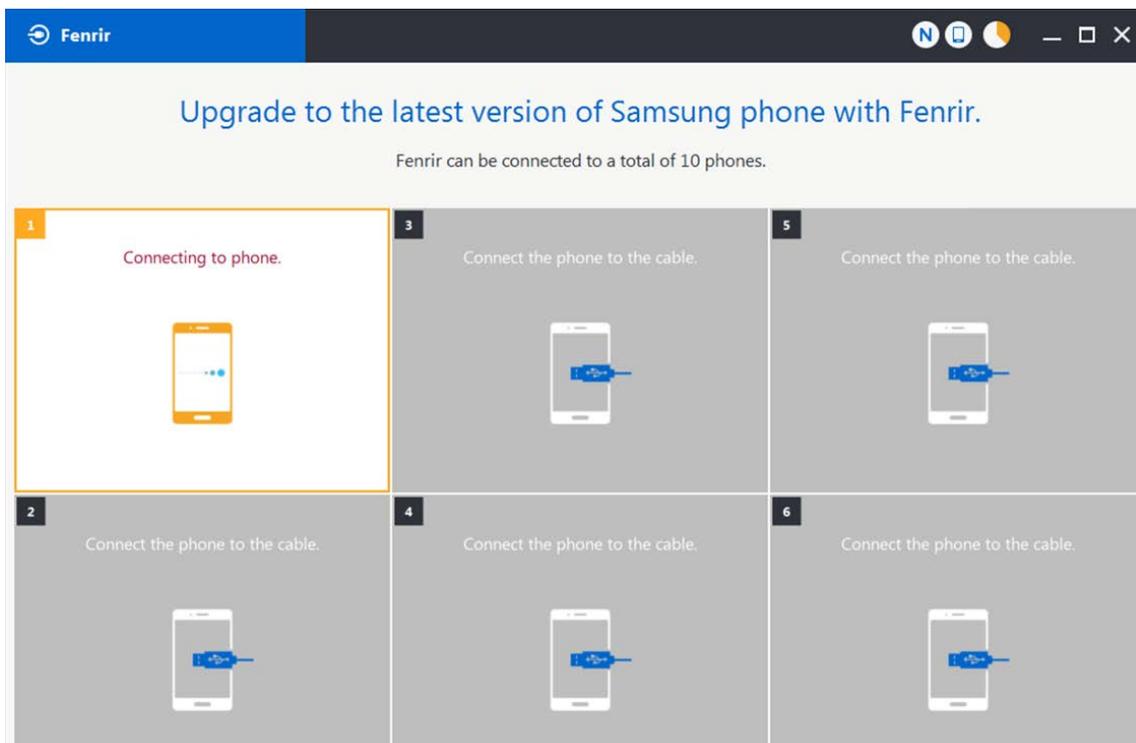
6. Level 1 Repair

3) Ensure device has sufficient charge (at least 20%) to start firmware update.



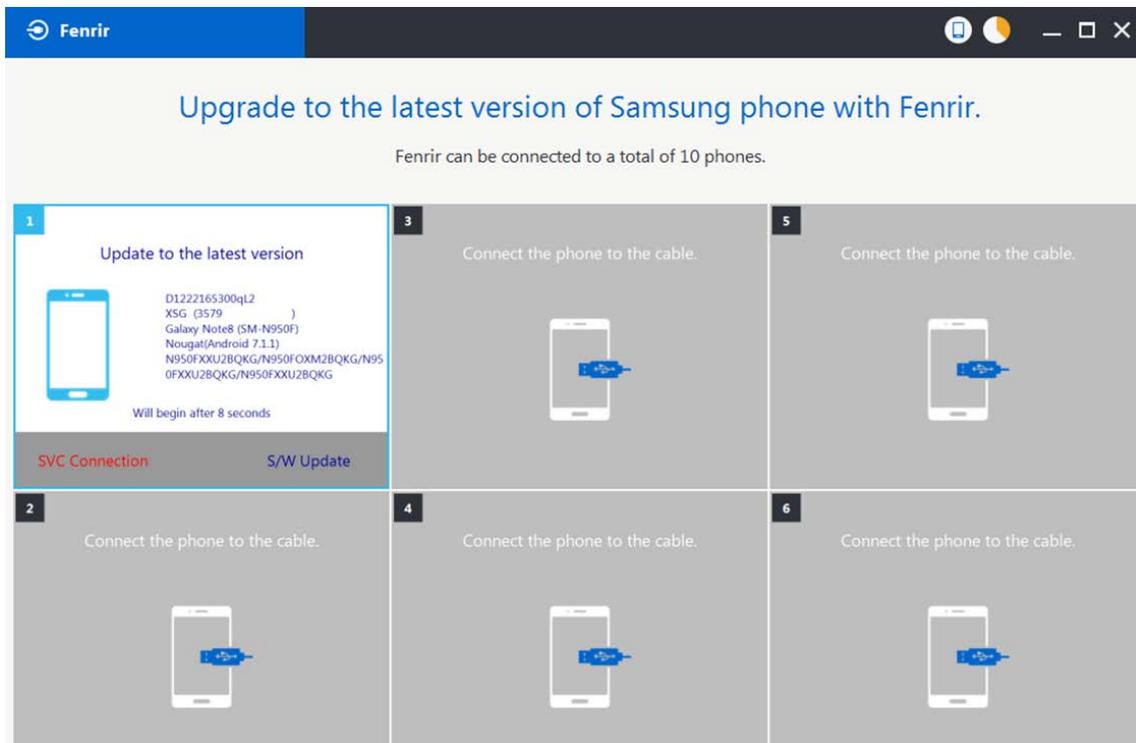
4) Connect the device to PC via data cable.

5) Upon USB connection, you will be presented with below screen.

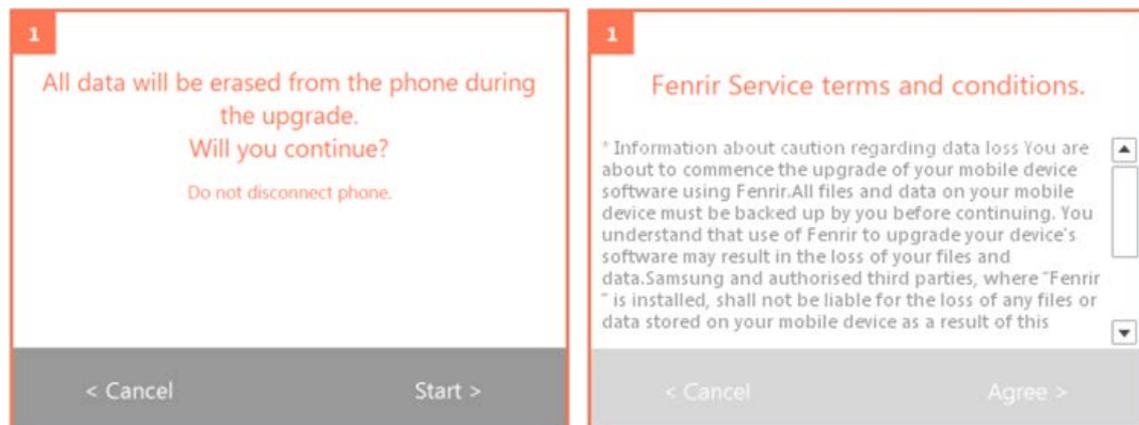


6. Level 1 Repair

6) Once device is detected, you will be presented with below screen. To update S/W, select “S/W Update” or to exit select “SVC Connection”. If you select “SVC Connection”, only Fenrir connection history (record) will be stored in the FUS server to support warranty validation. (This is known as “Service Connection” history)

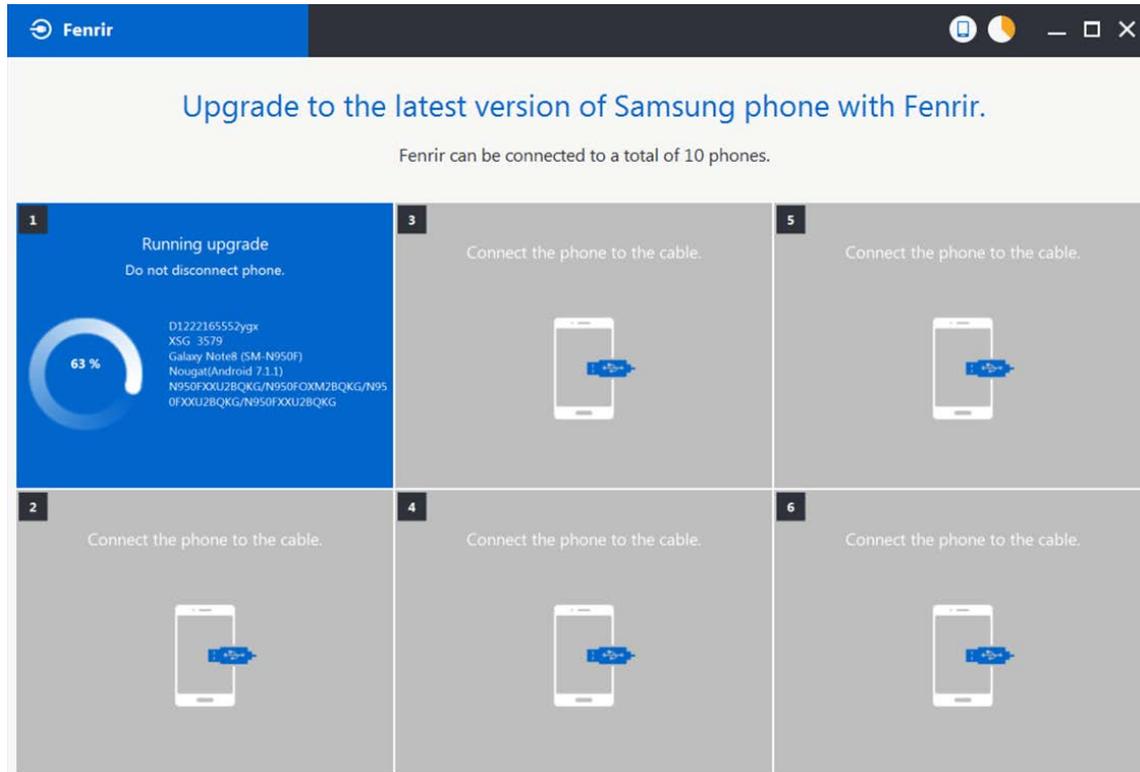


7) Once Fenrir starts, application will display the below screen. And select the Start button & Agree button.

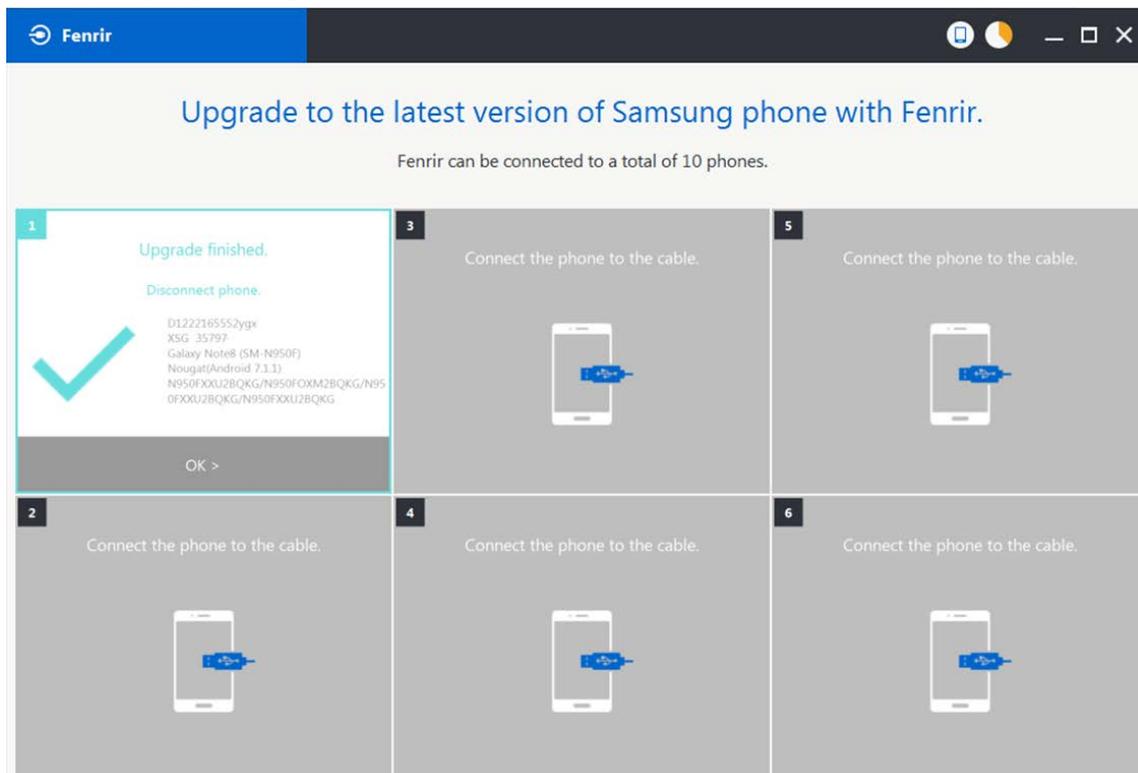


6. Level 1 Repair

8) The status circle increases as the update installs. The update process takes approximately 5-10 minutes to complete. Do not disconnect the device from USB during processing.



9) Once complete, application will present the below screen indicating update complete. Click Ok and detach device from USB.



6. Level 1 Repair

6-2. How to use 'Odin' program

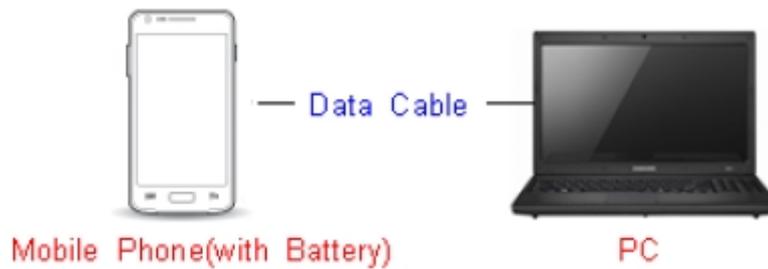
※ S/W Update via Fenrir is mandatory.

Below is the method to use 'Odin' program in any specific case.

6-2-1. Preparation

- Installation program : [Odin3 v3.13.2.exe or above](#)
- Mobile Phone
- Data Cable
- S/W Binary files (downloaded from GSPN)

※ Settings

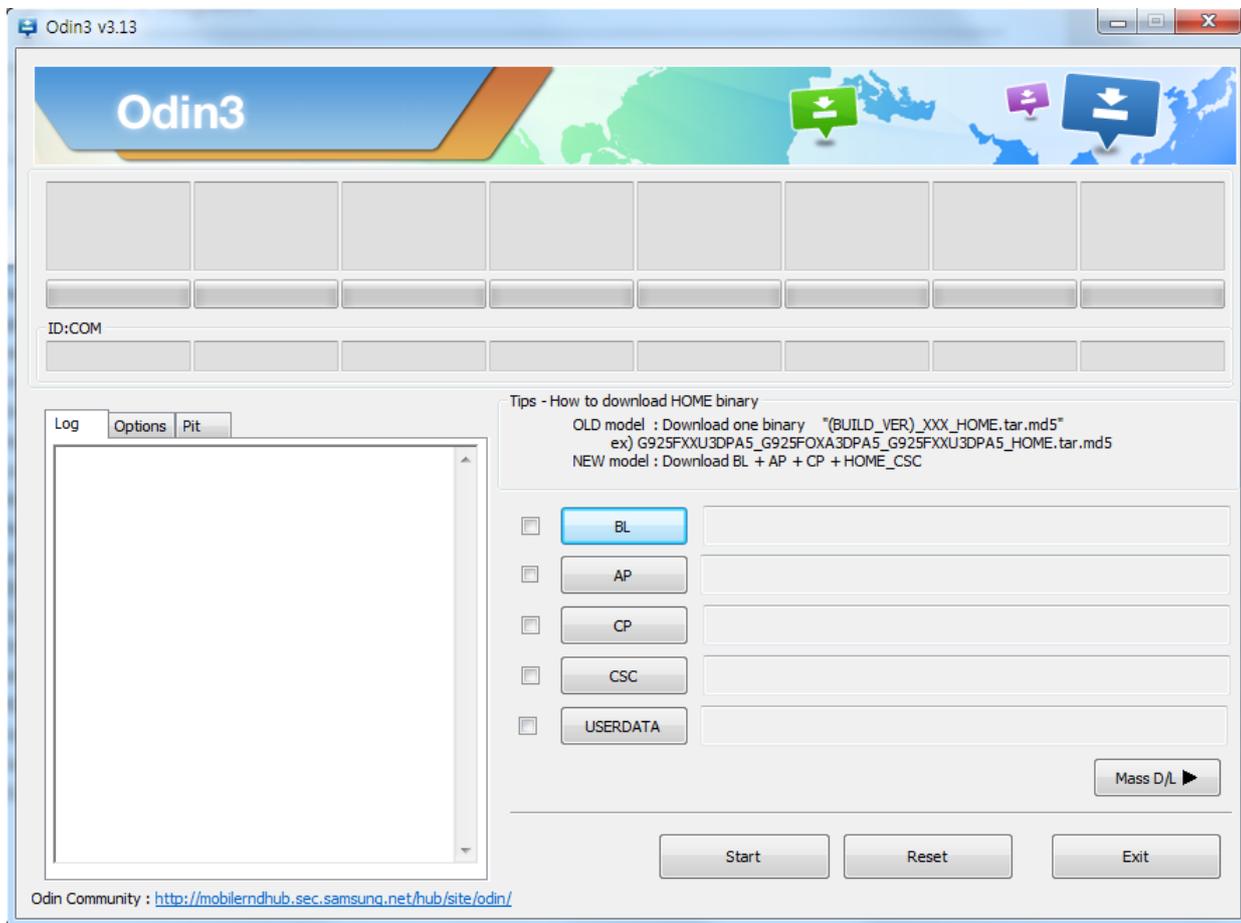


Data Cable : [GH39-01949A](#)

6. Level 1 Repair

6-2-2. S/W Installation Program (Downloader program)

Open up the S/W Installation Program by executing the "**Odin3 v3.13.2.exe**"

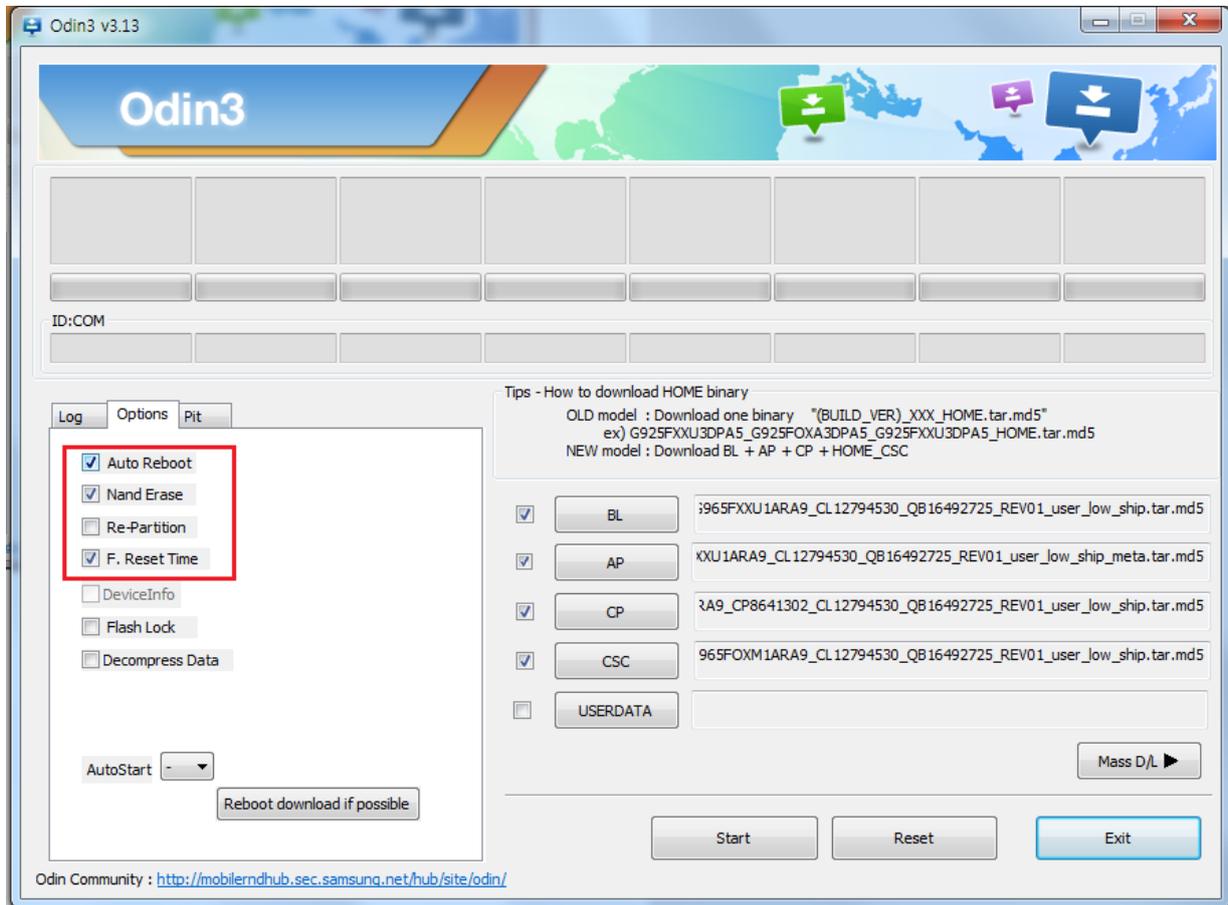


6. Level 1 Repair

1. Enable the check mark by click on the following options

- Check Auto Reboot, F. Reset Time, Nand Erase
- Check BL, AP, CP, CSC Files

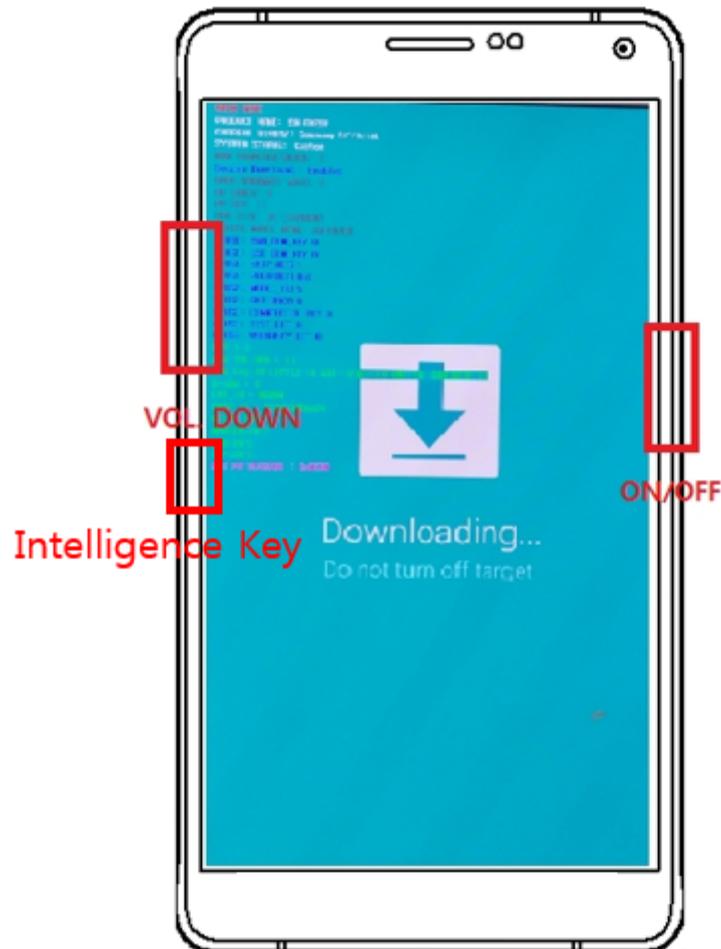
* Note : "Odin v3.13.2 or above" checks MD5 checksum just after file selection.



6. Level 1 Repair

2. Enter into Download Mode

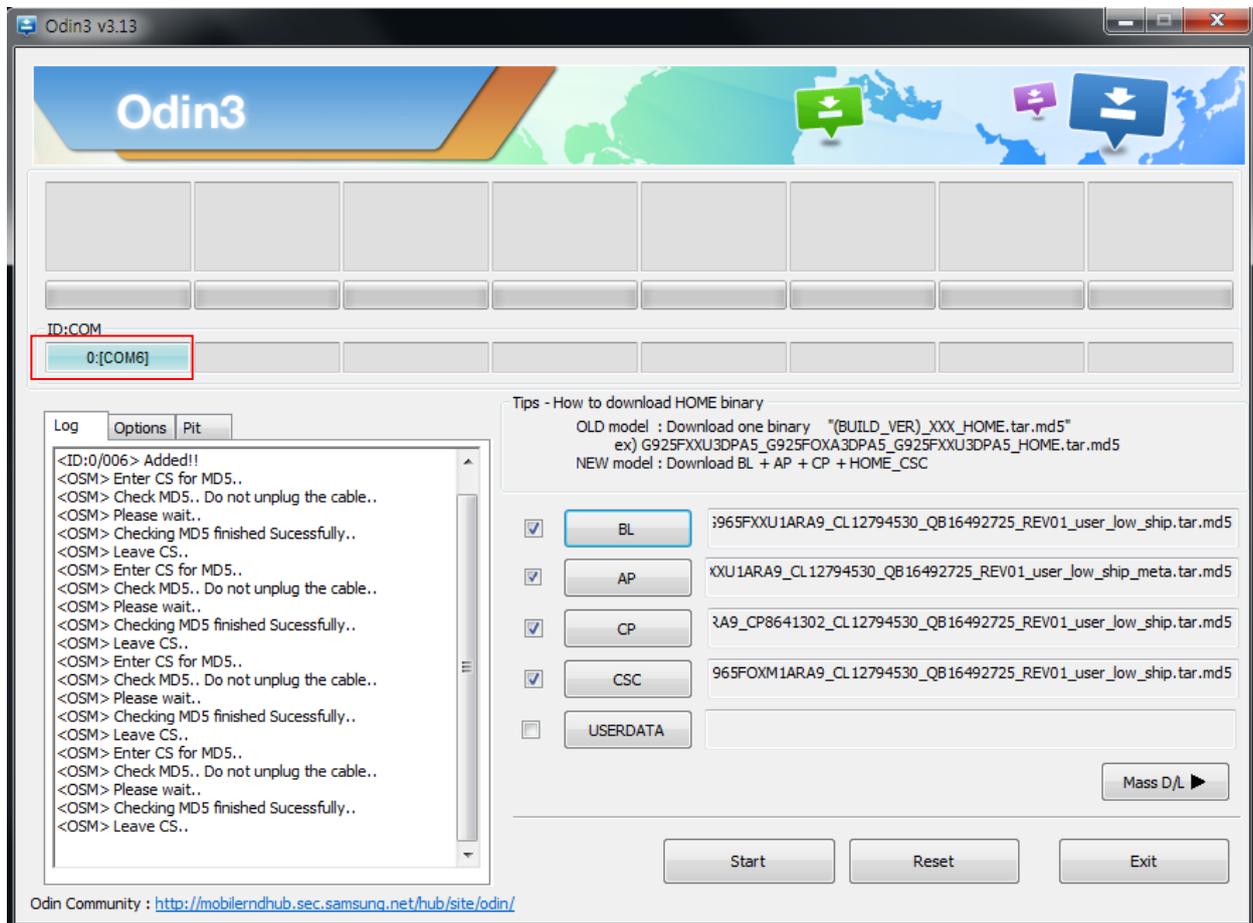
- Enter into Download Mode by pressing Volume Down button, Intelligence button and ON/OFF Button simultaneously followed by pressing Volume up button as a direction of the phone.



6. Level 1 Repair

3. Connect the device to PC via Data Cable.

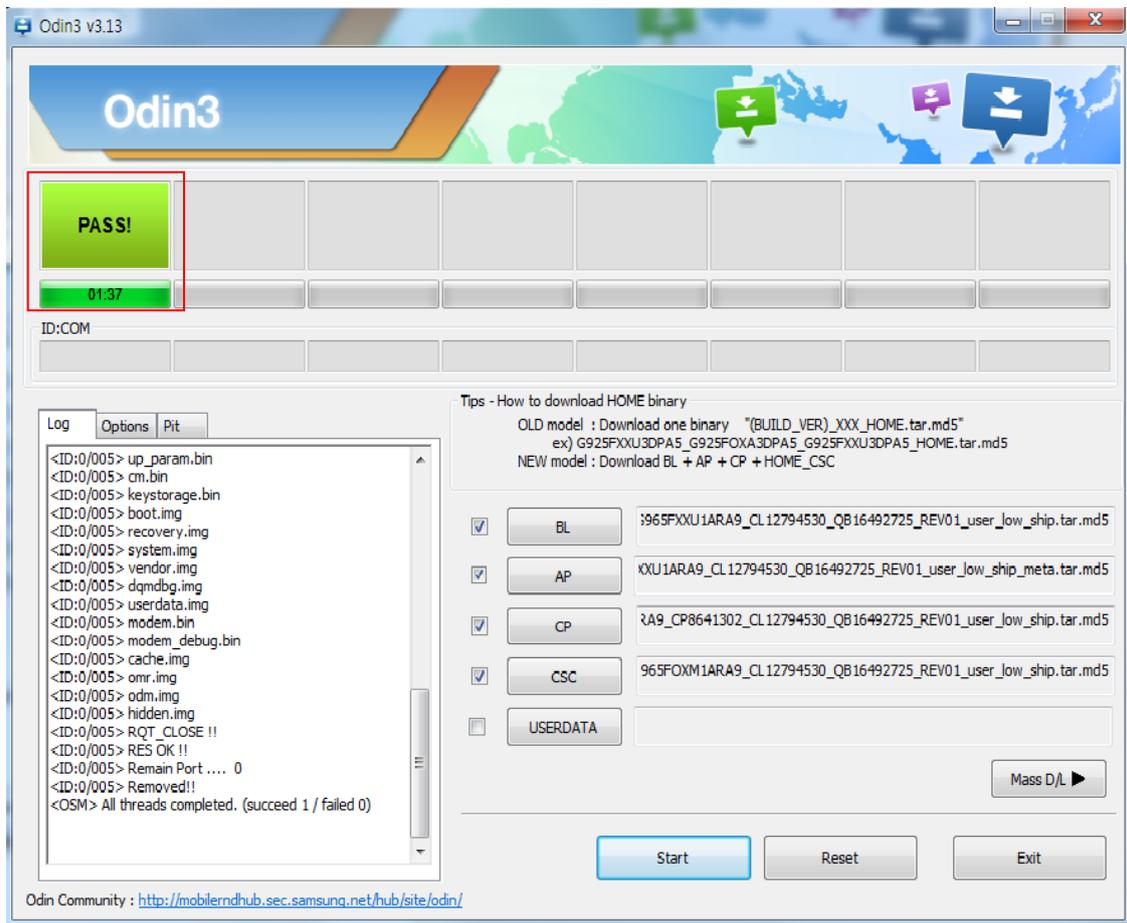
Make sure that the one of communication ports [ID:COM] box is highlighted in sky blue. The device is now connected with the PC and ready to download the binary files in it.



6. Level 1 Repair

4. Start downloading the binary files into the device by clicking Start button on the screen.

The green colored "PASS!" sign will appear on the upper-left box if the binary files have been successfully downloaded into the device.



5. Disconnect the device from the Data cable.

6. Once the device boots up, you can check the version of the binary file or name by pressing the following code in sequence; ***#1234#**

You can perform Factory data Reset by Settings → General Management → Reset

※ Caution. Never disconnect during the S/W downloading.

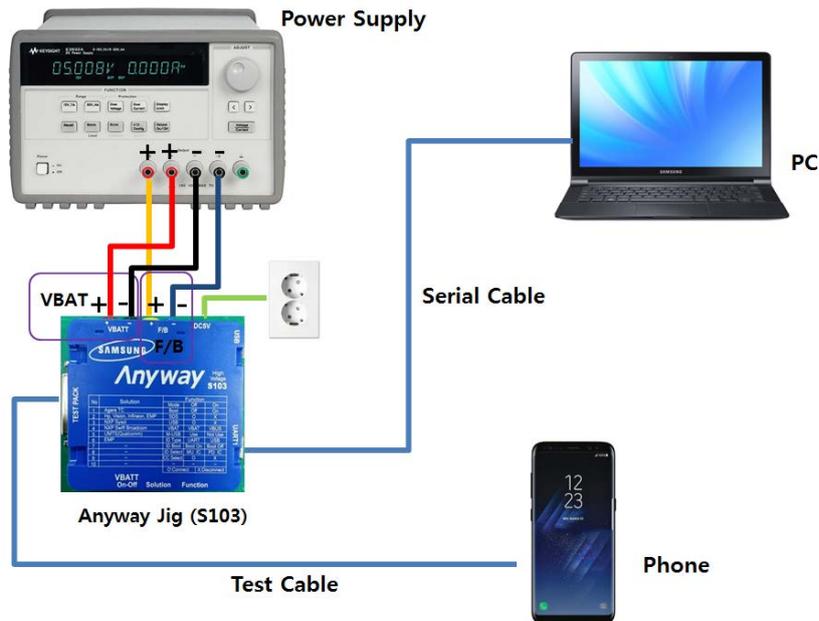
6. Level 1 Repair

6-3. IMEI writing

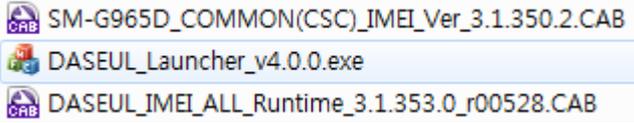
6-3-1. Preparation

- New IMEI writing Program has been released.
- Supported Model : Models which CAB files are uploaded on HHPsvc INI File category, instead of ini file.
- Refer to below IMEI writing procedure.

- H/W



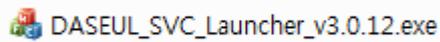
- S/W

① Library Install	To use Daseul, library files should be installed. Refer to SVC Bulletin “(11-82) Daseul (New IMEI writing Program) Library Install guide_rev1.0”
② Launcher	DASEUL_SVC_Launcher_v3.0.12 or higher -Uploaded on HHPsvc Notice
③ Runtime File	1. DASEUL_IMEI_ALL_Runtime_3.1.353.0_r00528.CAB or higher -Uploaded on HHPsvc Notice 2. Make 'ModelName' folder at the same position with launcher & Runtime file. 
④ Model File	Copy Model File under the 'Model Name' folder

6. Level 1 Repair

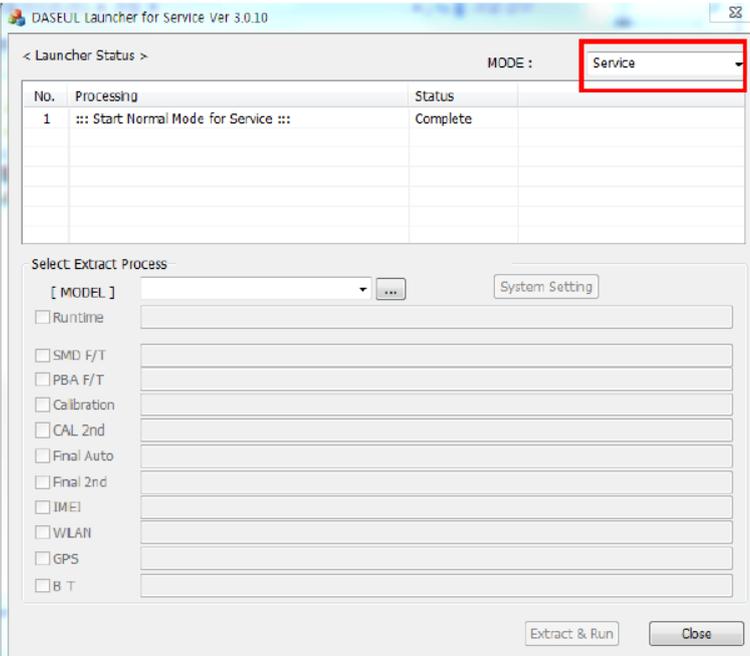
6-3-2. IMEI writing Process

1. Run DASEUL_SVC_Launcher_v3.0.12.exe

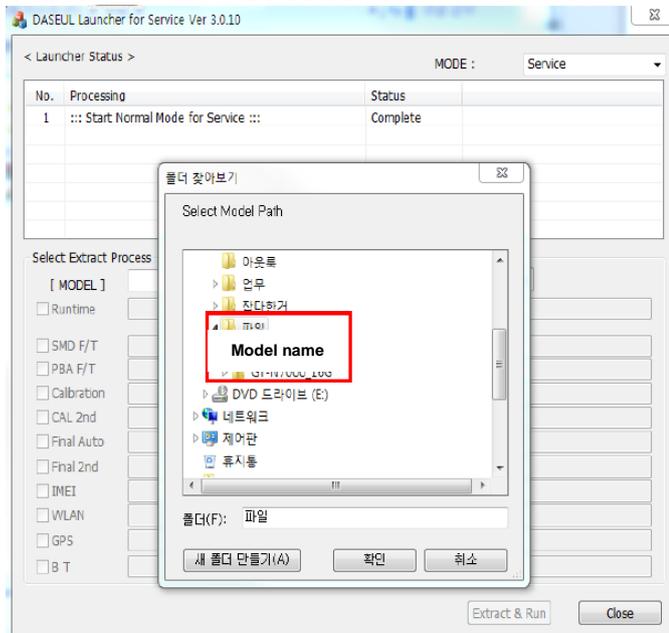


DASEUL_SVC_Launcher_v3.0.12.exe

2. Select Service Mode

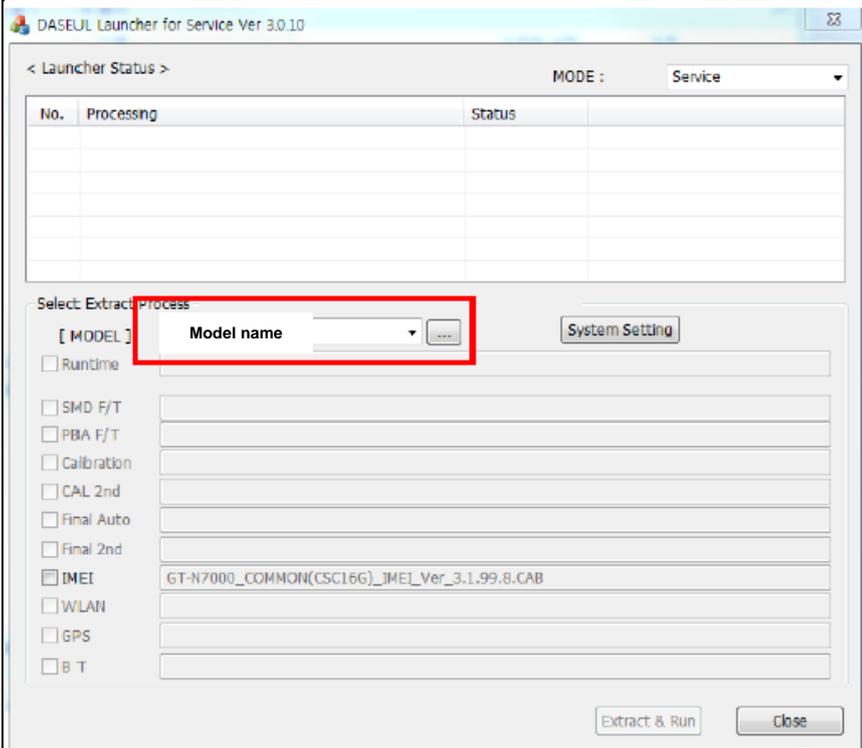


3. Click  and Select folder where the Launcher exists



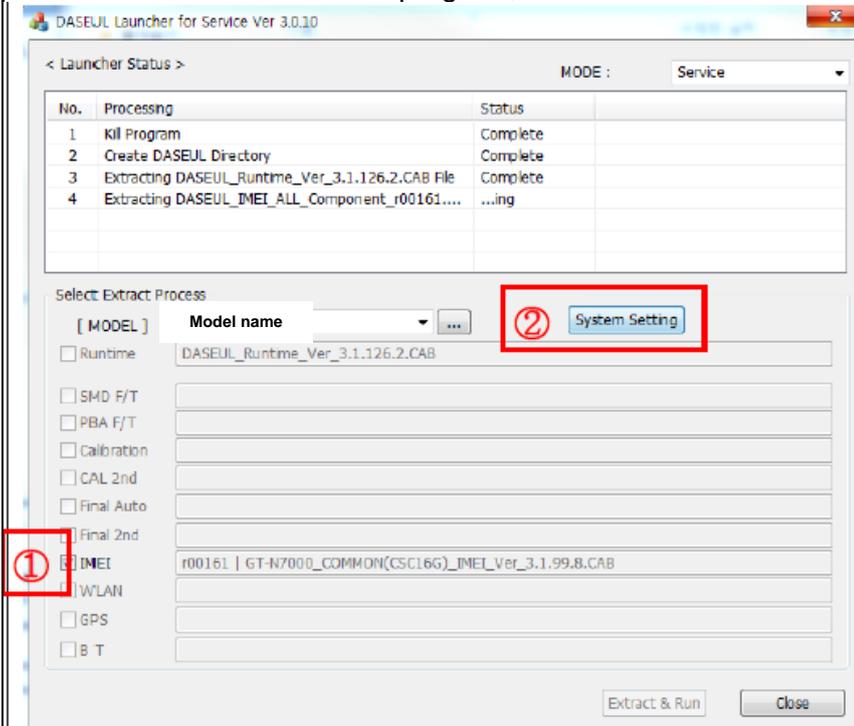
6. Level 1 Repair

4. Select Model



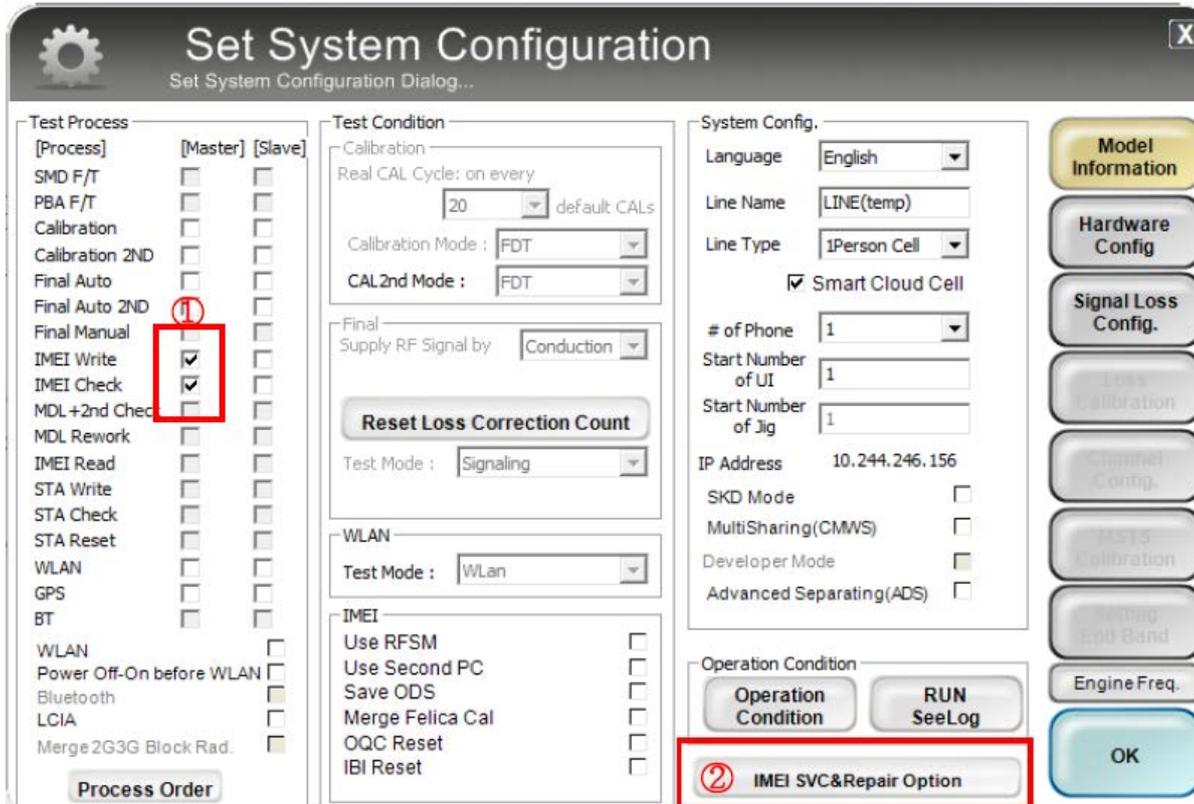
5. Check IMEI and click System Setting

※ Once you setup the setting, you don't have to do it again, unless there is change. From second run of the IMEI program, check IMEI and click Extract & Run.



6. Level 1 Repair

6. Check IMEI Write / IMEI Check and click IMEI SVC & Repair Option.



Set System Configuration
Set System Configuration Dialog...

Test Process

[Process]	[Master]	[Slave]
SMD F/T	<input type="checkbox"/>	<input type="checkbox"/>
PBA F/T	<input type="checkbox"/>	<input type="checkbox"/>
Calibration	<input type="checkbox"/>	<input type="checkbox"/>
Calibration 2ND	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto 2ND	<input type="checkbox"/>	<input type="checkbox"/>
Final Manual	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Write	<input checked="" type="checkbox"/>	<input type="checkbox"/>
IMEI Check	<input checked="" type="checkbox"/>	<input type="checkbox"/>
MDL +2nd Check	<input type="checkbox"/>	<input type="checkbox"/>
MDL Rework	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Read	<input type="checkbox"/>	<input type="checkbox"/>
STA Write	<input type="checkbox"/>	<input type="checkbox"/>
STA Check	<input type="checkbox"/>	<input type="checkbox"/>
STA Reset	<input type="checkbox"/>	<input type="checkbox"/>
WLAN	<input type="checkbox"/>	<input type="checkbox"/>
GPS	<input type="checkbox"/>	<input type="checkbox"/>
BT	<input type="checkbox"/>	<input type="checkbox"/>
WLAN	<input type="checkbox"/>	<input type="checkbox"/>
Power Off-On before WLAN	<input type="checkbox"/>	<input type="checkbox"/>
Bluetooth	<input type="checkbox"/>	<input type="checkbox"/>
LCIA	<input type="checkbox"/>	<input type="checkbox"/>
Merge 2G3G Block Rad.	<input type="checkbox"/>	<input type="checkbox"/>

Test Condition

Calibration
Real CAL Cycle: on every default CALs

Calibration Mode :

CAL2nd Mode :

Final
Supply RF Signal by :

Reset Loss Correction Count

Test Mode :

WLAN
Test Mode :

IMEI
Use RFSM
Use Second PC
Save ODS
Merge Felica Cal
OQC Reset
IBI Reset

System Config.

Language :

Line Name :

Line Type :

Smart Cloud Cell

of Phone :

Start Number of UI :

Start Number of Jig :

IP Address : 10.244.246.156

SKD Mode

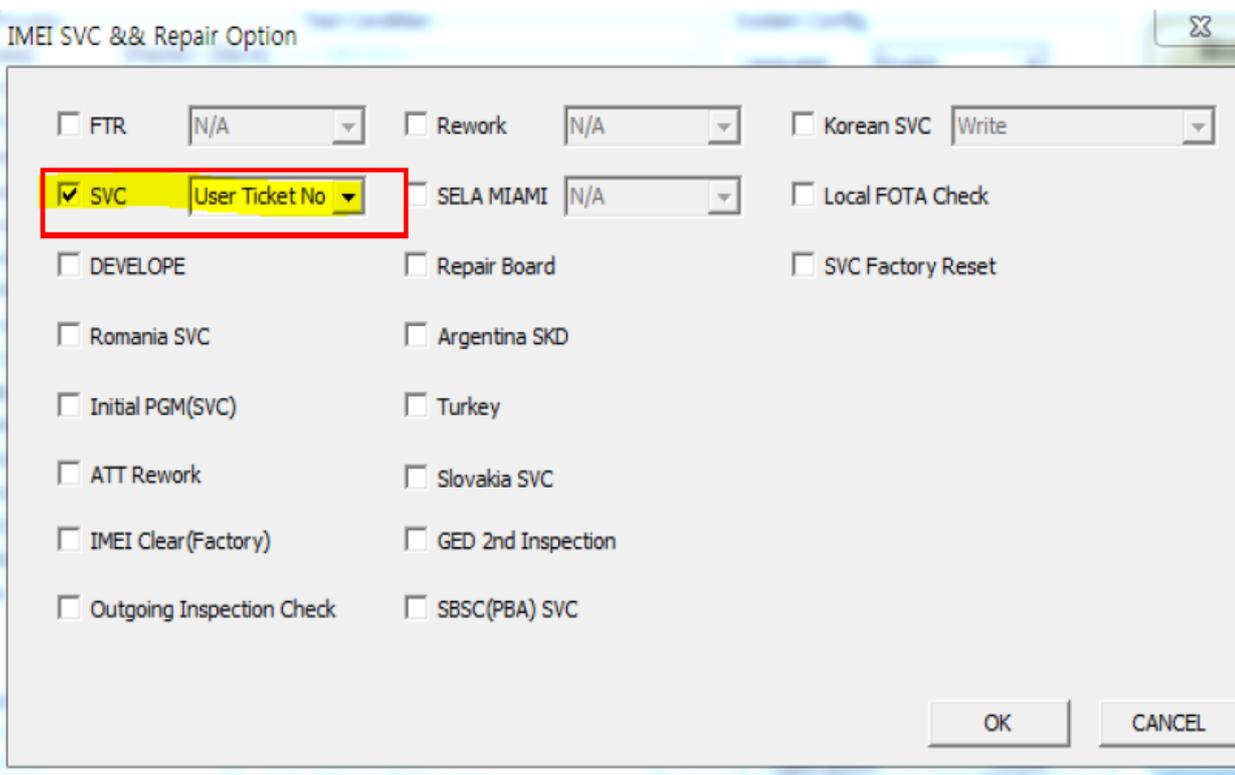
MultiSharing(CMWS)

Developer Mode

Advanced Separating(ADS)

Operation Condition

7. Check 'SVC , User Ticket No' and click OK



IMEI SVC & Repair Option

FTR Rework Korean SVC

SVC SELA MIAMI Local FOTA Check

DEVELOPE Repair Board SVC Factory Reset

Romania SVC Argentina SKD

Initial PGM(SVC) Turkey

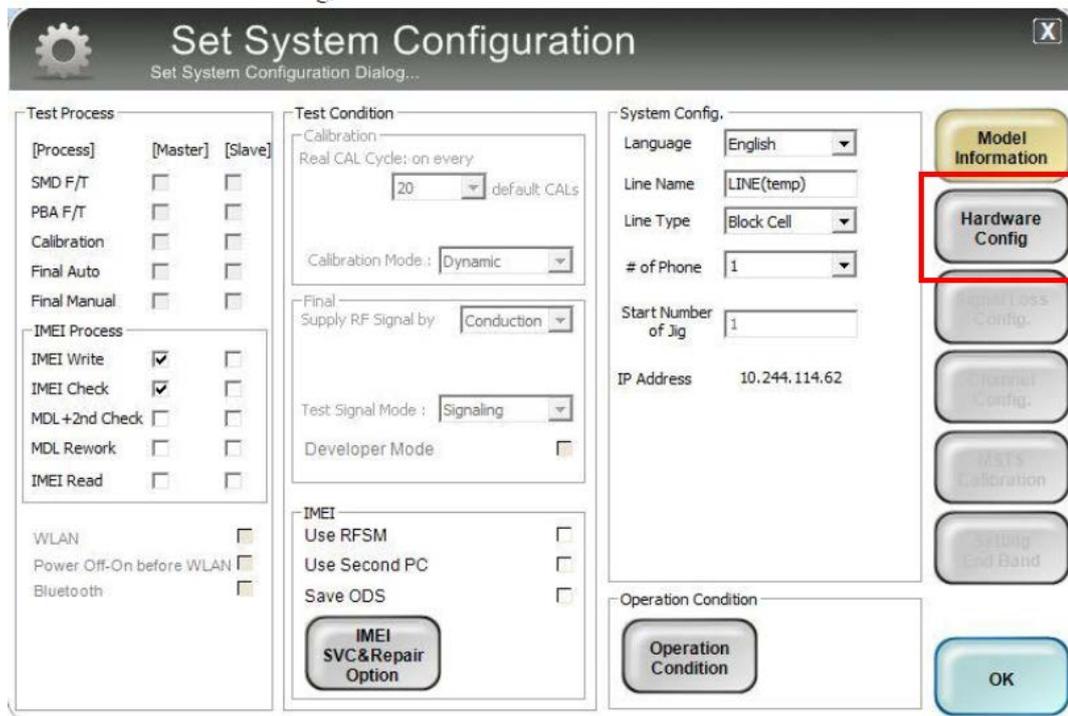
ATT Rework Slovakia SVC

IMEI Clear(Factory) GED 2nd Inspection

Outgoing Inspection Check SBSC(PBA) SVC

6. Level 1 Repair

8. Click 'Hardware Config'



Set System Configuration
Set System Configuration Dialog...

Test Process

[Process]	[Master]	[Slave]
SMD F/T	<input type="checkbox"/>	<input type="checkbox"/>
PBA F/T	<input type="checkbox"/>	<input type="checkbox"/>
Calibration	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto	<input type="checkbox"/>	<input type="checkbox"/>
Final Manual	<input type="checkbox"/>	<input type="checkbox"/>

IMEI Process

IMEI Write	<input checked="" type="checkbox"/>	<input type="checkbox"/>
IMEI Check	<input checked="" type="checkbox"/>	<input type="checkbox"/>
MDL+2nd Check	<input type="checkbox"/>	<input type="checkbox"/>
MDL Rework	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Read	<input type="checkbox"/>	<input type="checkbox"/>

WLAN
Power Off-On before WLAN
Bluetooth

Test Condition

Calibration
Real CAL Cycle: on every
20 default CALs
Calibration Mode: Dynamic

Final
Supply RF Signal by: Conduction

Test Signal Mode: Signaling
Developer Mode

IMEI

Use RFSM
Use Second PC
Save ODS

System Config.

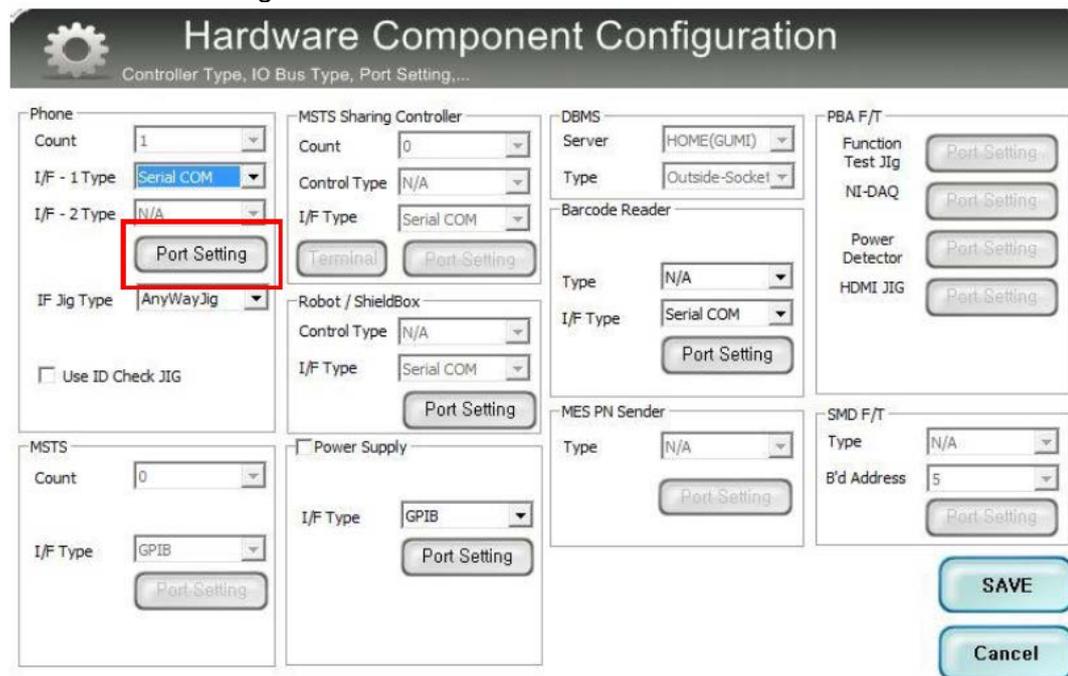
Language: English
Line Name: LINE(temp)
Line Type: Block Cell
of Phone: 1
Start Number of Jig: 1
IP Address: 10.244.114.62

Operation Condition

Model Information
Hardware Config
Signal Loss Config.
Terminal Config.
MSTs Calibration
Setting End Band

IMEI SVC&Repair Option
Operation Condition
OK

9. Click 'Port Setting'



Hardware Component Configuration
Controller Type, IO Bus Type, Port Setting,...

Phone

Count: 1
I/F - 1 Type: Serial COM
I/F - 2 Type: N/A
IF Jig Type: AnyWayJig
 Use ID Check JIG

MSTS Sharing Controller

Count: 0
Control Type: N/A
I/F Type: Serial COM
Terminal
Port Setting

Robot / ShieldBox

Control Type: N/A
I/F Type: Serial COM
Port Setting

Power Supply

I/F Type: GPIB
Port Setting

DBMS

Server: HOME(GUMI)
Type: Outside-Socket

Barcode Reader

Type: N/A
I/F Type: Serial COM
Port Setting

MES PN Sender

Type: N/A
Port Setting

PBA F/T

Function Test Jig
NI-DAQ
Power Detector
HDMI JIG
Port Setting
Port Setting
Port Setting
Port Setting

MSTS

Count: 0
I/F Type: GPIB
Port Setting

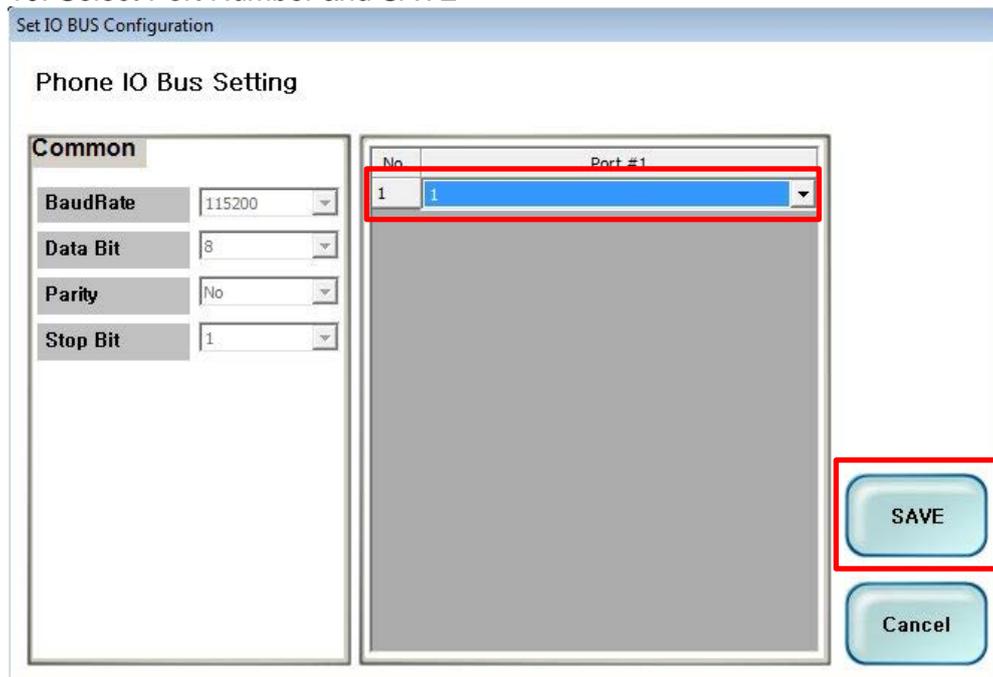
SMD F/T

Type: N/A
B'd Address: 5
Port Setting

SAVE
Cancel

6. Level 1 Repair

10. Select Port Number and SAVE



Set IO BUS Configuration

Phone IO Bus Setting

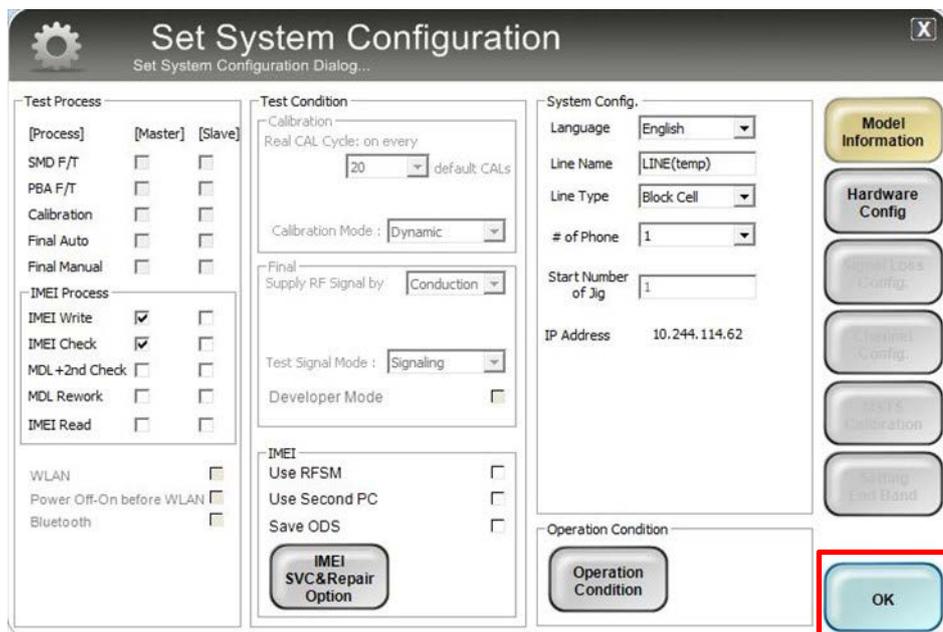
Common

BaudRate: 115200
Data Bit: 8
Parity: No
Stop Bit: 1

No.	Port #1
1	1

SAVE
Cancel

11. Click OK to proceed



Set System Configuration
Set System Configuration Dialog...

Test Process

[Process] [Master] [Slave]

SMD F/T
PBA F/T
Calibration
Final Auto
Final Manual
IMEI Process
IMEI Write
IMEI Check
MDL +2nd Check
MDL Rework
IMEI Read
WLAN
Power Off-On before WLAN
Bluetooth

Test Condition

Calibration
Real CAL Cycle: on every
20 default CALs
Calibration Mode: Dynamic
Final
Supply RF Signal by: Conduction
Test Signal Mode: Signaling
Developer Mode
IMEI
Use RFSM
Use Second PC
Save ODS
IMEI SVC&Repair Option

System Config.

Language: English
Line Name: LINE(temp)
Line Type: Block Cell
of Phone: 1
Start Number of Jig: 1
IP Address: 10.244.114.62

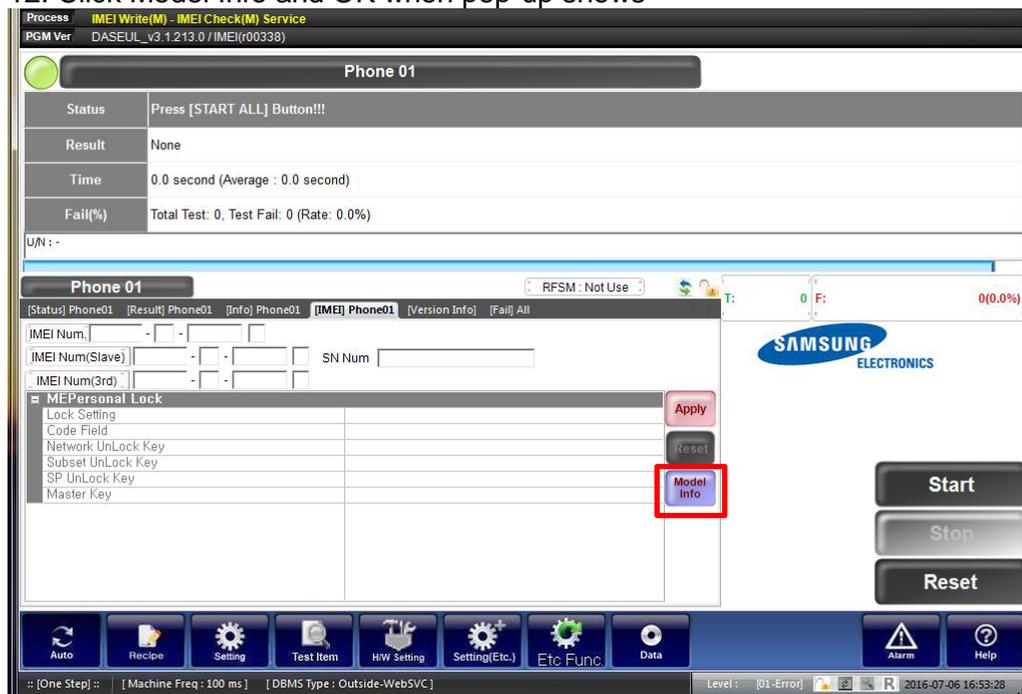
Operation Condition

Operation Condition

Model Information
Hardware Config
Signal Loss Config.
Channel Config.
Factory Calibration
Setting End Band
OK

6. Level 1 Repair

12. Click Model Info and OK when pop-up shows



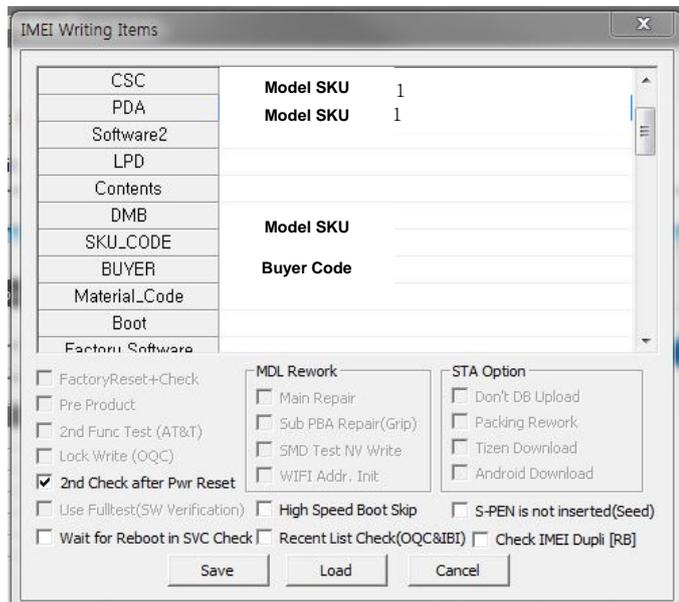
13. Click OK



6. Level 1 Repair

14. Input SKU_CODE and BUYER, then click Save button.

※ Refer to HHPsvc→IMEI Review to check SKU Code and buyer



IMEI Writing Items

CSC	Model SKU	1
PDA	Model SKU	1
Software2		
LPD		
Contents		
DMB	Model SKU	
SKU_CODE		
BUYER	Buyer Code	
Material_Code		
Boot		
Factory Software		

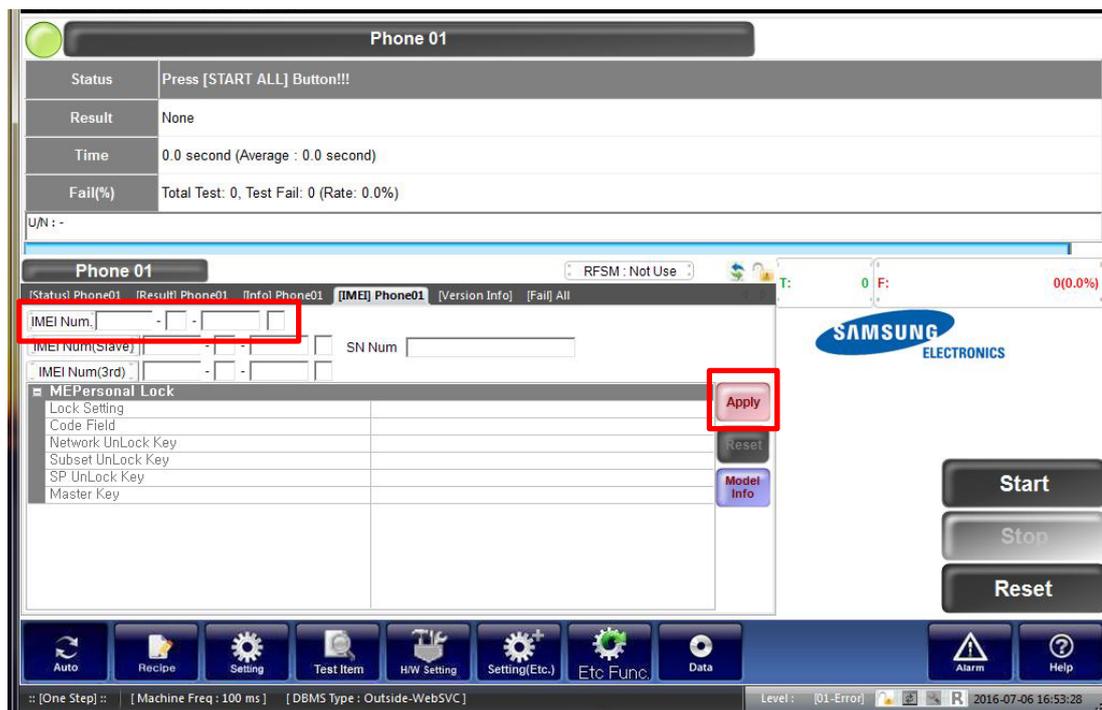
FactoryReset+Check
 Pre Product
 2nd Func. Test (AT&T)
 Lock Write (OQC)
 2nd Check after Pwr Reset
 Use Fulltest(SW Verification)
 Wait for Reboot in SVC Check

MDL Rework
 Main Repair
 Sub PBA Repair(Grip)
 SMD Test NY Write
 WIFI Addr. Init
 High Speed Boot Skip
 Recent List Check(OQC&IBI)

STA Option
 Don't DB Upload
 Packing Rework
 Tizen Download
 Android Download
 S-PEN is not inserted(Seed)
 Check IMEI Dupli [RB]

Save Load Cancel

15. Input IMEI Number and click Apply



Phone 01

Status: Press [START ALL] Button!!!

Result: None

Time: 0.0 second (Average : 0.0 second)

Fail(%): Total Test: 0, Test Fail: 0 (Rate: 0.0%)

U/N: -

Phone 01

RFSM: Not Use

T: 0 F: 0(0.0%)

IMEI Num. [Red Box]

IMEI Num(Slave)

IMEI Num(3rd)

SN Num

MEPersonal Lock

Lock Setting

Code Field

Network UnLock Key

Subset UnLock Key

SP UnLock Key

Master Key

Apply [Red Box]

Reset

Model Info

Start

Stop

Reset

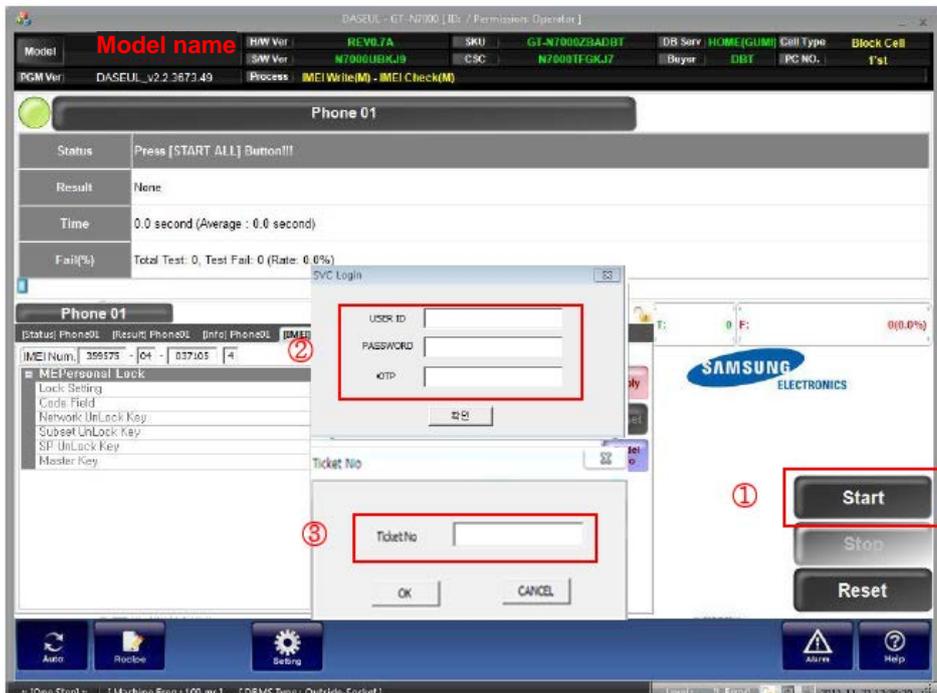
Auto Recipe Setting Test Item HW Setting Setting[Etc.] Etc Func. Data

Alarm Help

Level : [01-Error] 2016-07-06 16:53:28

6. Level 1 Repair

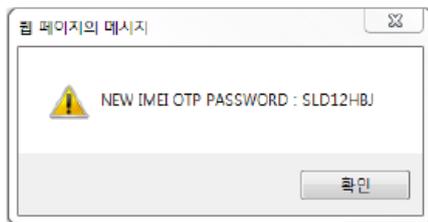
16. ① Click Start → ② Input IMEI writing ID and Password & OTP → ③ Input Ticket No



※ OTP(One time Password) : OTP is valid for 6 hours.

After that, you can get new OTP by click the “Forgotten your IMEI OTP PW or Create new IMEI OTP PW” button.

☞ OTP Location : GSPN → Knowledge → HHP svc → Home

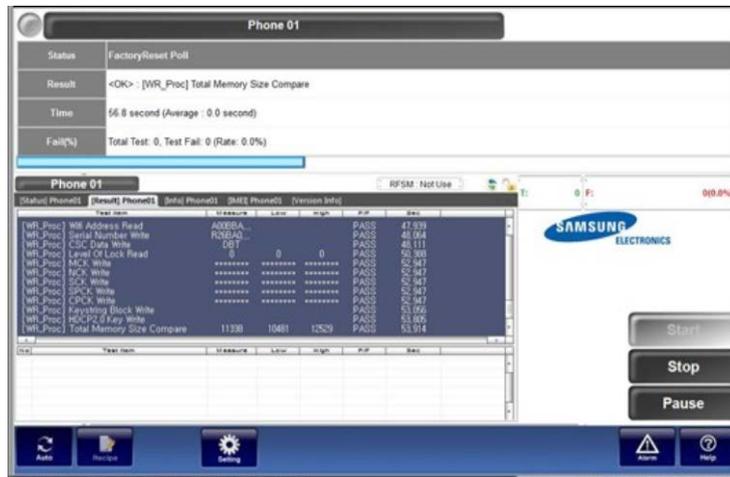


6. Level 1 Repair

17. Connect the phone to Anyway JIG

- ✧ When you connect the phone, the phone should be turned off.
After connecting the phone, the phone will be booted automatically.

18. IMEI Writing Proceeding



Phone 01

Status: Factory/Reset Poll

Result: <OK> : [WR_Proc] Total Memory Size Compare

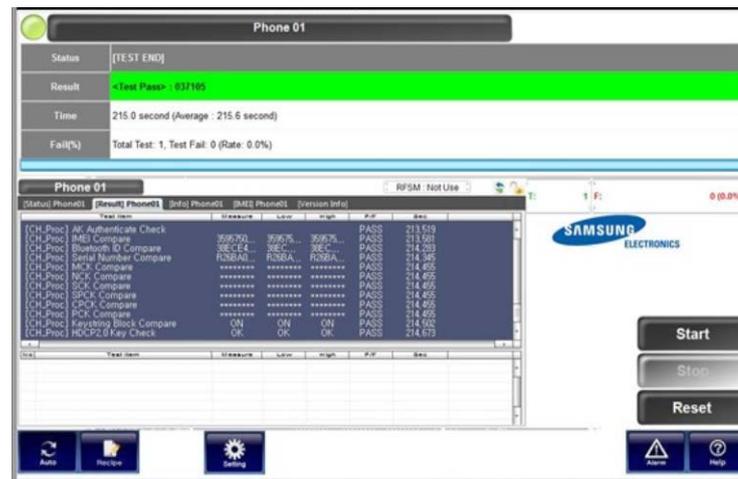
Time: 56.8 second (Average : 0.0 second)

Fail(%): Total Test: 0, Test Fail: 0 (Rate: 0.0%)

Test Item	Measure	Low	High	P.F.P	Res
WR_Proc	IMEI Address Read	000000...	000000...	PASS	47.639
WR_Proc	Serial Number Write	R0B0A...	R0B0A...	PASS	48.004
WR_Proc	CSC Data Write	0B7	0	PASS	48.111
WR_Proc	Level 0 Lock Read	0	0	PASS	50.388
WR_Proc	MCK Write	*****	*****	PASS	52.347
WR_Proc	NCK Write	*****	*****	PASS	52.347
WR_Proc	SPCK Write	*****	*****	PASS	52.347
WR_Proc	CPCK Write	*****	*****	PASS	52.347
WR_Proc	Keystring Block Write	*****	*****	PASS	53.006
WR_Proc	HDCP2.0 Key Write	*****	*****	PASS	53.006
WR_Proc	Total Memory Size Compare	11330	10461 12529	PASS	53.914

Buttons: Start, Stop, Pause

19. IMEI Writing Success



Phone 01

Status: [TEST END]

Result: <Test Pass> : 037195

Time: 215.0 second (Average : 215.6 second)

Fail(%): Total Test: 1, Test Fail: 0 (Rate: 0.0%)

Test Item	Measure	Low	High	P.F.P	Res
CH_Proc	AK Authenticate Check	30970...	30970...	PASS	213.519
CH_Proc	IMEI Compare	30970...	30970...	PASS	213.561
CH_Proc	Brwathwh 0 Compare	30C14...	30C14...	PASS	214.029
CH_Proc	Serial Number Compare	R0B0A...	R0B0A...	PASS	214.345
CH_Proc	MCK Compare	*****	*****	PASS	214.455
CH_Proc	NCK Compare	*****	*****	PASS	214.455
CH_Proc	SPCK Compare	*****	*****	PASS	214.455
CH_Proc	CPCK Compare	*****	*****	PASS	214.455
CH_Proc	Keystring Compare	ON	ON	PASS	214.502
CH_Proc	Keystring Compare	ON	ON	PASS	214.502
CH_Proc	HDCP2.0 Key Check	OK	OK	PASS	214.673

Buttons: Start, Stop, Reset

6. Level 1 Repair

6-4. RF Calibration

6-4-1. Required items in order to calibrate RF

- Installation program: RF Calibration Program
- Daseul_Launcher_vx.x.xx.exe
- Daseul_CAL_ALL_Runtime_x.x.xxx.x.CAB
- Model File
- : **SM-xxxx_OPEN_CALIBRATION_Ver_x.x.xxx.x.CAB**

※ **It is required to use the latest program.**

- Mobile Phone
- R&S CMW500
- E3632A Power Supply
- GPIB Cable (2ea)
- JIG BOX (S103)
- Adapter
- UART Serial Cable
- IF Cable (GH81-11962W)

❖ Table of test cables

RF Cable (Manual)	GH81-11962M (2ea)	GH81-11962U (2ea)	
	1.2T, 102mm 	1.2T, 102mm 	
4 Port Divider	GH81-11962A	GH81-11962B	GH81-11962E
	Divider 	Divider Cable 	50Ω terminator 

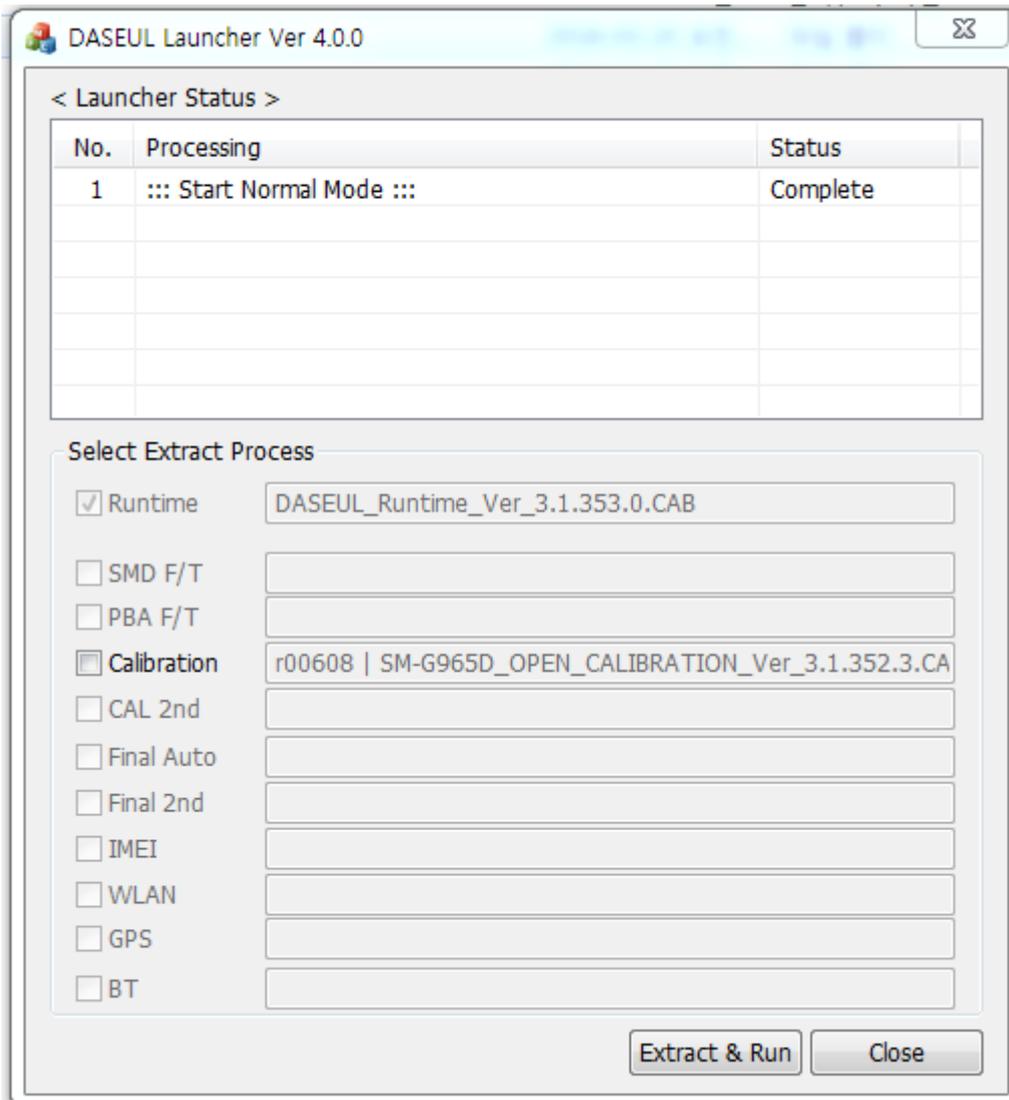
6. Level 1 Repair

6-4-2. RF Calibration Program

1. Run the RF Calibration Program Launcher, 'DASEUL_Launcher_vx.x.xx.exe'.

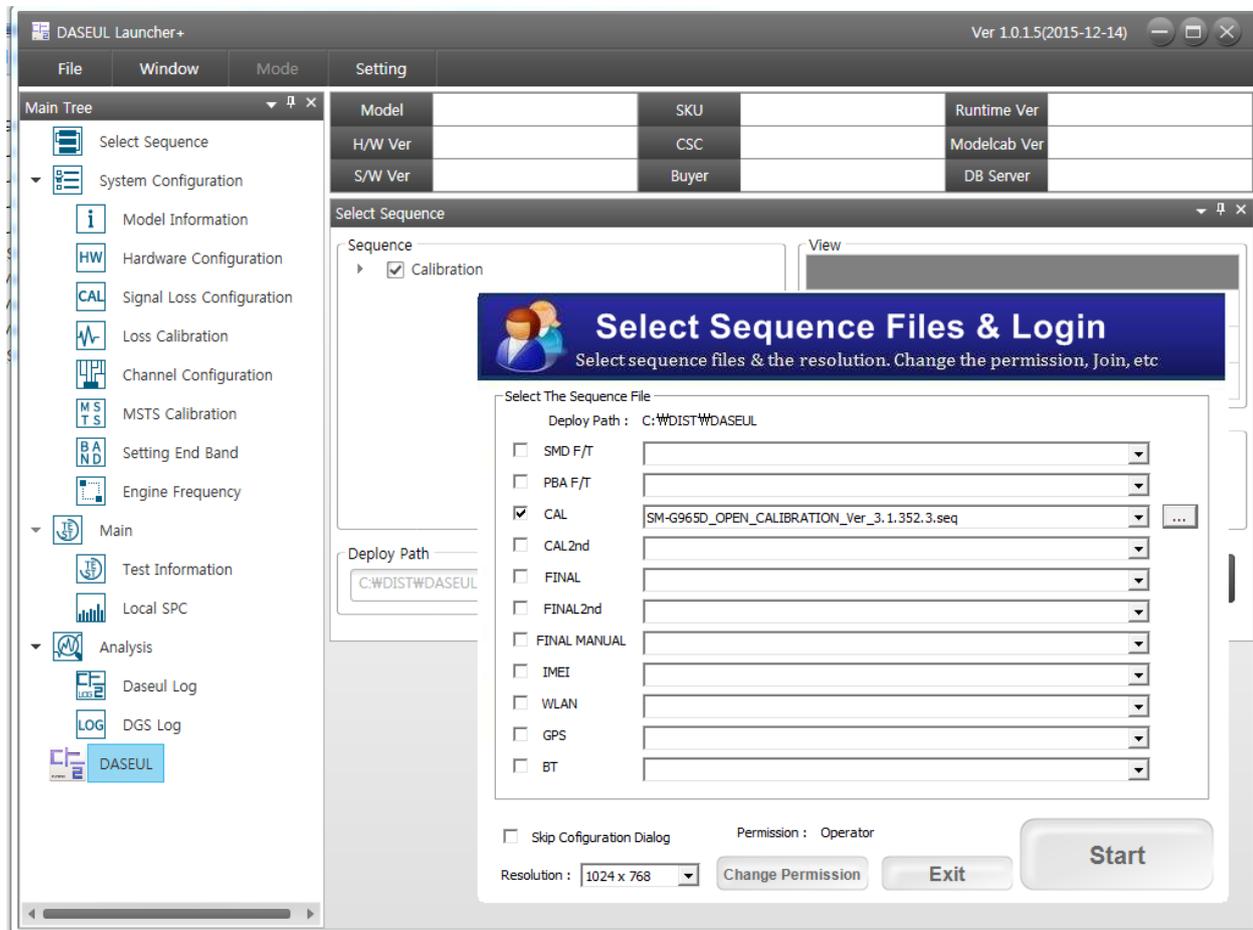
-  SM-G965D_OPEN_CALIBRATION_Ver_3.1.352.3.CAB
-  DASEUL_Launcher_v4.0.0.exe
-  DASEUL_CAL_ALL_Runtime_3.1.353.0_r00608.CAB

2. Check the 'Calibration' option and Click 'Extract & Run'.



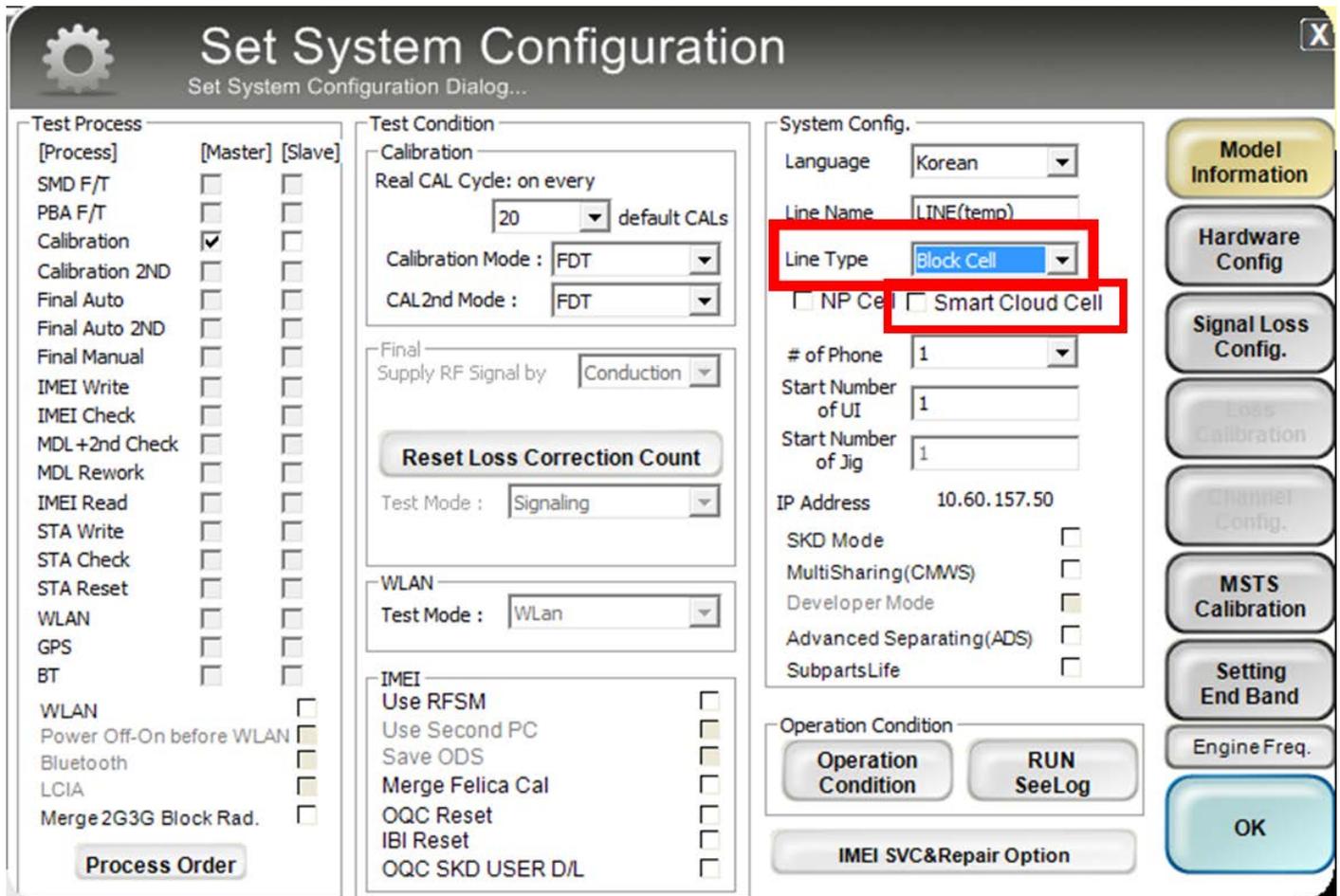
6. Level 1 Repair

3. Check the 'CAL' and open the [model file](#), then select 'Start' button.



6. Level 1 Repair

4. Change the Line Type to 'Block Cell' and disable 'Smart Cloud Cell'.



Set System Configuration
Set System Configuration Dialog...

Test Process

[Process]	[Master]	[Slave]
SMD F/T	<input type="checkbox"/>	<input type="checkbox"/>
PBA F/T	<input type="checkbox"/>	<input type="checkbox"/>
Calibration	<input checked="" type="checkbox"/>	<input type="checkbox"/>
Calibration 2ND	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto 2ND	<input type="checkbox"/>	<input type="checkbox"/>
Final Manual	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Write	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Check	<input type="checkbox"/>	<input type="checkbox"/>
MDL +2nd Check	<input type="checkbox"/>	<input type="checkbox"/>
MDL Rework	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Read	<input type="checkbox"/>	<input type="checkbox"/>
STA Write	<input type="checkbox"/>	<input type="checkbox"/>
STA Check	<input type="checkbox"/>	<input type="checkbox"/>
STA Reset	<input type="checkbox"/>	<input type="checkbox"/>
WLAN	<input type="checkbox"/>	<input type="checkbox"/>
GPS	<input type="checkbox"/>	<input type="checkbox"/>
BT	<input type="checkbox"/>	<input type="checkbox"/>
WLAN	<input type="checkbox"/>	<input type="checkbox"/>
Power Off-On before WLAN	<input type="checkbox"/>	<input type="checkbox"/>
Bluetooth	<input type="checkbox"/>	<input type="checkbox"/>
LCIA	<input type="checkbox"/>	<input type="checkbox"/>
Merge 2G3G Block Rad.	<input type="checkbox"/>	<input type="checkbox"/>

Test Condition

Calibration
Real CAL Cycle: on every
20 default CALs
Calibration Mode : FDT
CAL2nd Mode : FDT

Final
Supply RF Signal by: Conduction
Reset Loss Correction Count
Test Mode : Signaling

WLAN
Test Mode : WLAN

IMEI
Use RFSM
Use Second PC
Save ODS
Merge Felica Cal
OQC Reset
IBI Reset
OQC SKD USER D/L

System Config.

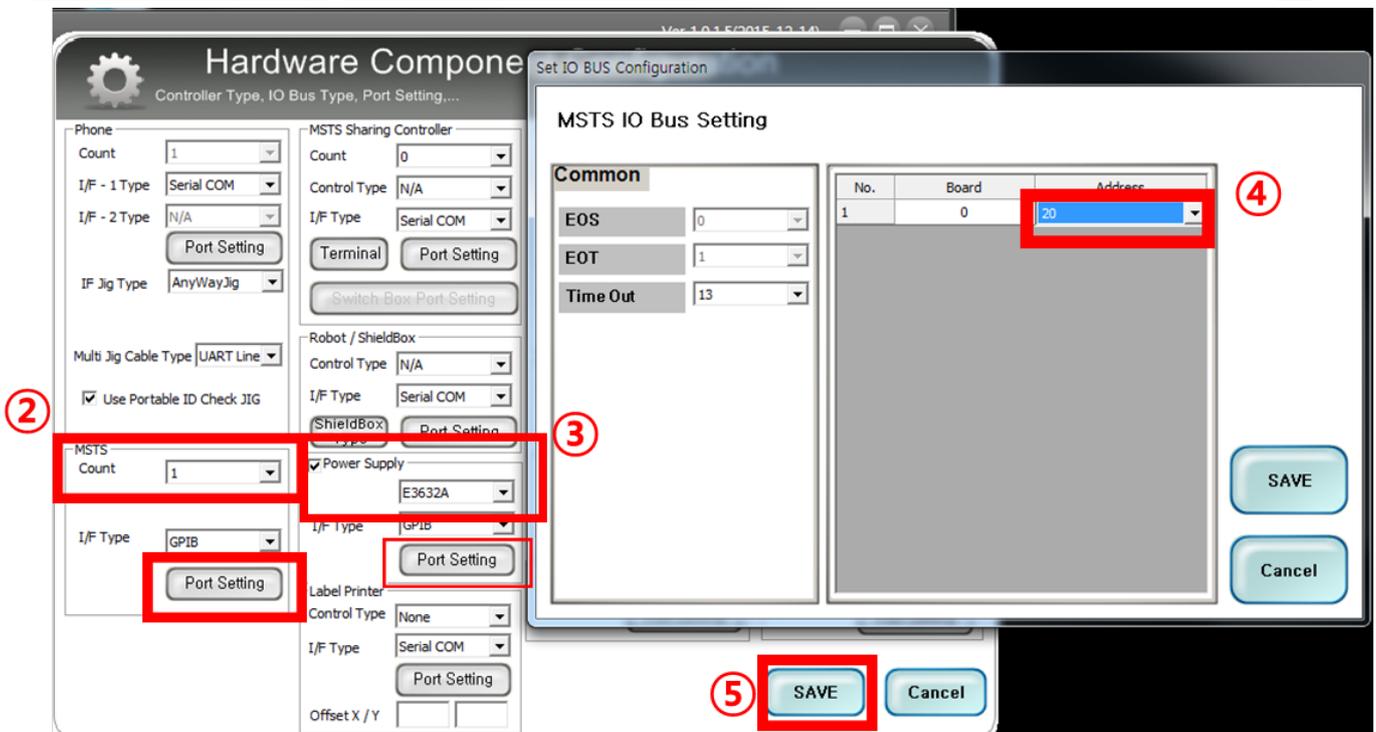
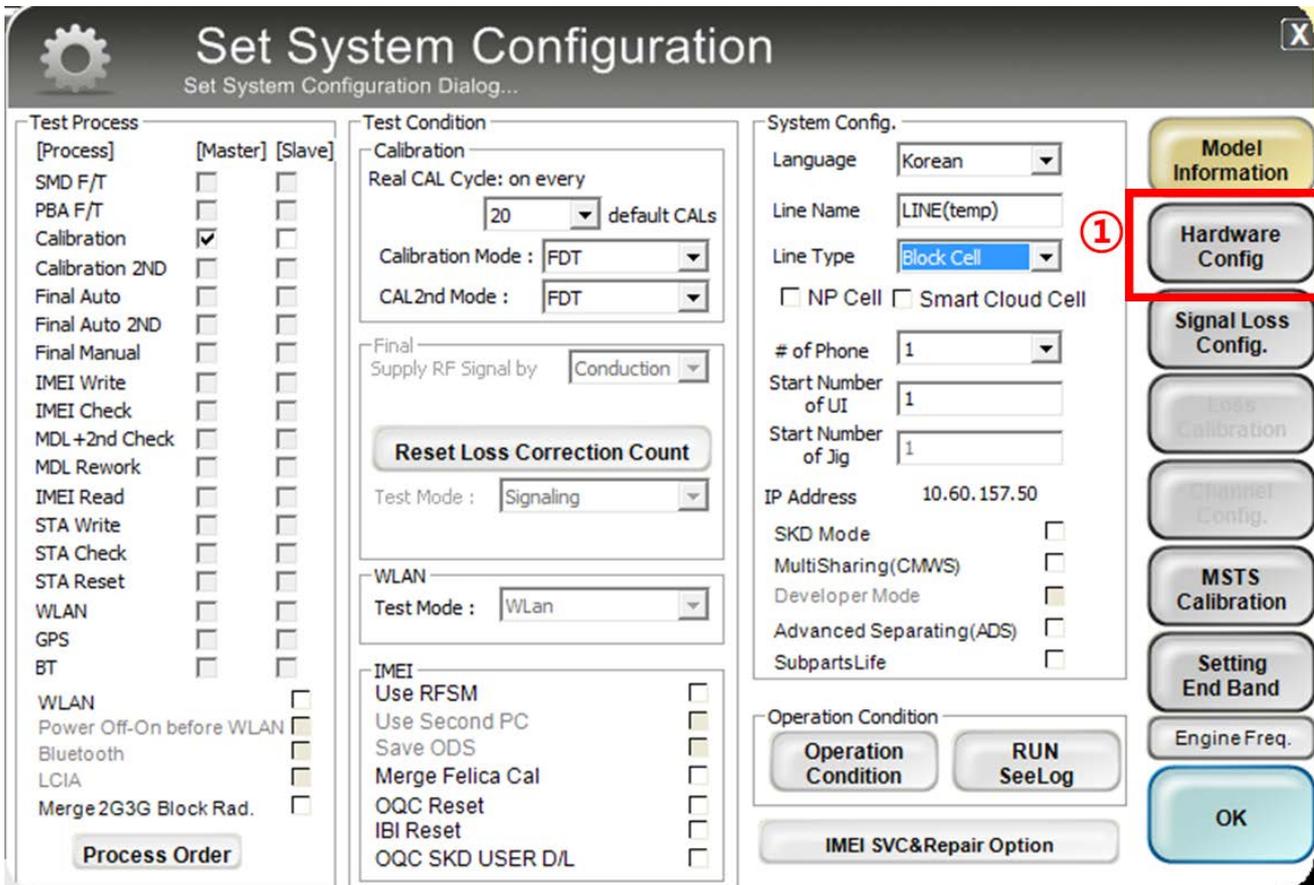
Language: Korean
Line Name: LINE(temp)
Line Type: Block Cell
 NP Cell Smart Cloud Cell
of Phone: 1
Start Number of UI: 1
Start Number of Jig: 1
IP Address: 10.60.157.50
SKD Mode
MultiSharing(CMWS)
Developer Mode
Advanced Separating(ADS)
SubpartsLife

Operation Condition
Operation Condition **RUN SeeLog**
IMEI SVC&Repair Option

Model Information
Hardware Config
Signal Loss Config.
Loss Calibration
Channel Config.
MSTS Calibration
Setting End Band
Engine Freq.
OK

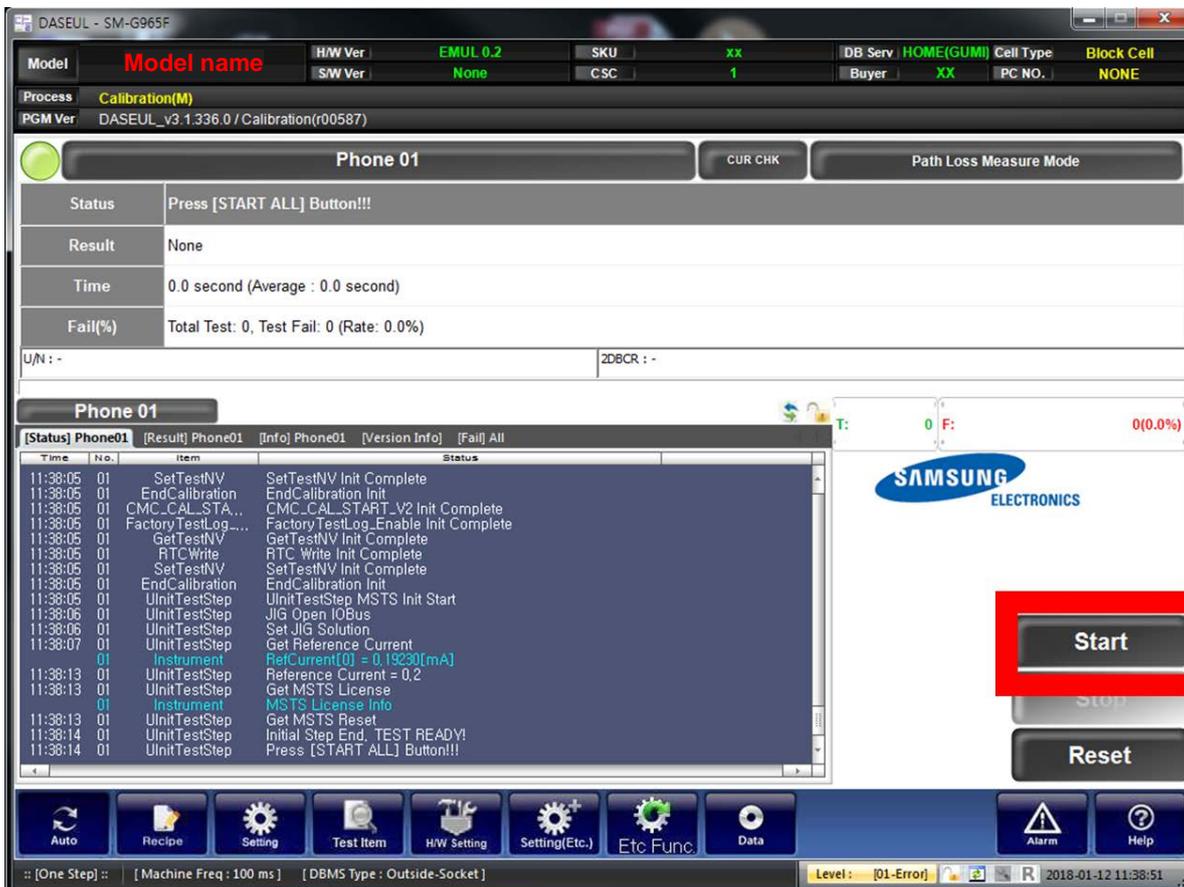
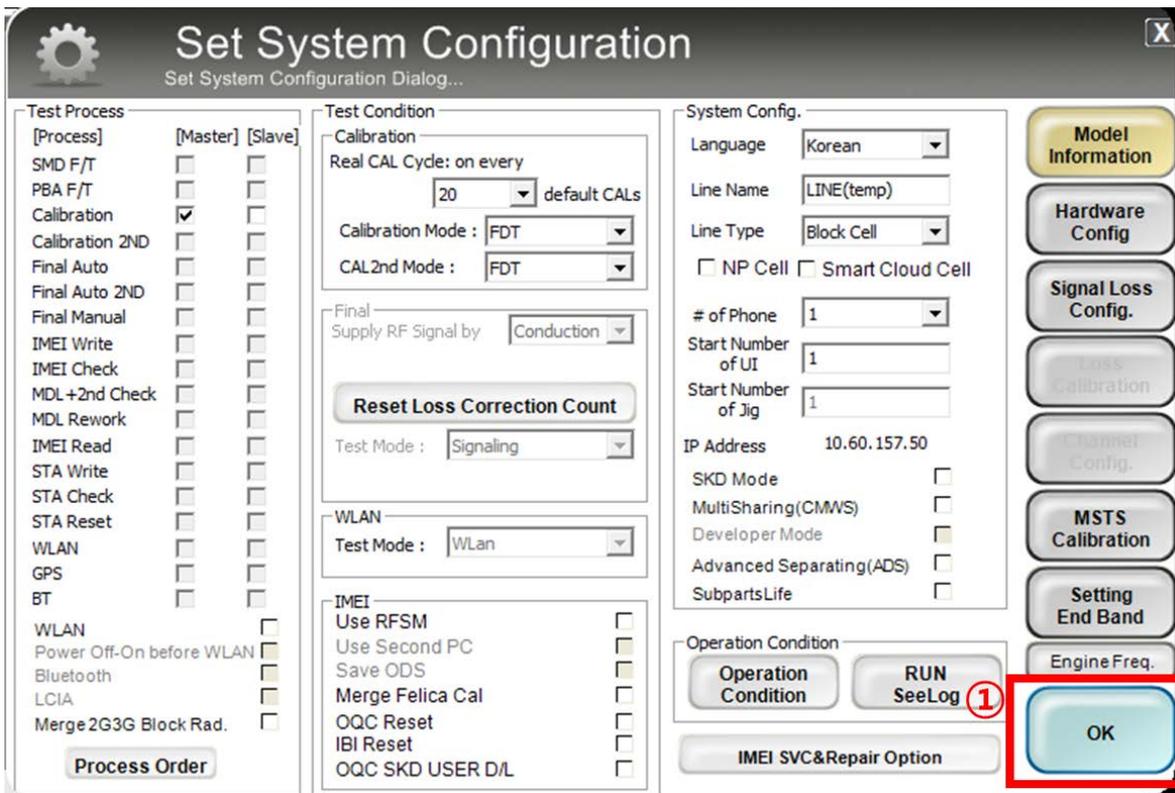
6. Level 1 Repair

5. Set the GPIB address of MSTS(CMW500) and Power Supply(E3632A) to enter 'Hardware Config' and 'Save'. (Check the GPIB address of equipments in advance)



6. Level 1 Repair

6. Press 'OK' to start RF Calibration after completing all settings.



9. Reference Abbreviation

Reference Abbreviation

- **AAC**: Advanced Audio Coding.
- **AVC** : Advanced Video Coding.
- **BER** : Bit Error Rate
- **BPSK**: Binary Phase Shift Keying
- **CA** : Conditional Access
- **CDM** : Code Division Multiplexing
- **C/I** : Carrier to Interference
- **DMB** : Digital Multimedia Broadcasting
- **EN** : European Standard
- **ES** : Elementary Stream
- **ETSI**: European Telecommunications Standards Institute
- **MPEG**: Moving Picture Experts Group
- **PN** : Pseudo-random Noise
- **PS** : Pilot Symbol
- **QPSK**: Quadrature Phase Shift Keying
- **RS** : Reed-Solomon
- **SI** : Service Information
- **TDM** : Time Division Multiplexing
- **TS** : Transport Stream